


# ***LCFC Confidential***

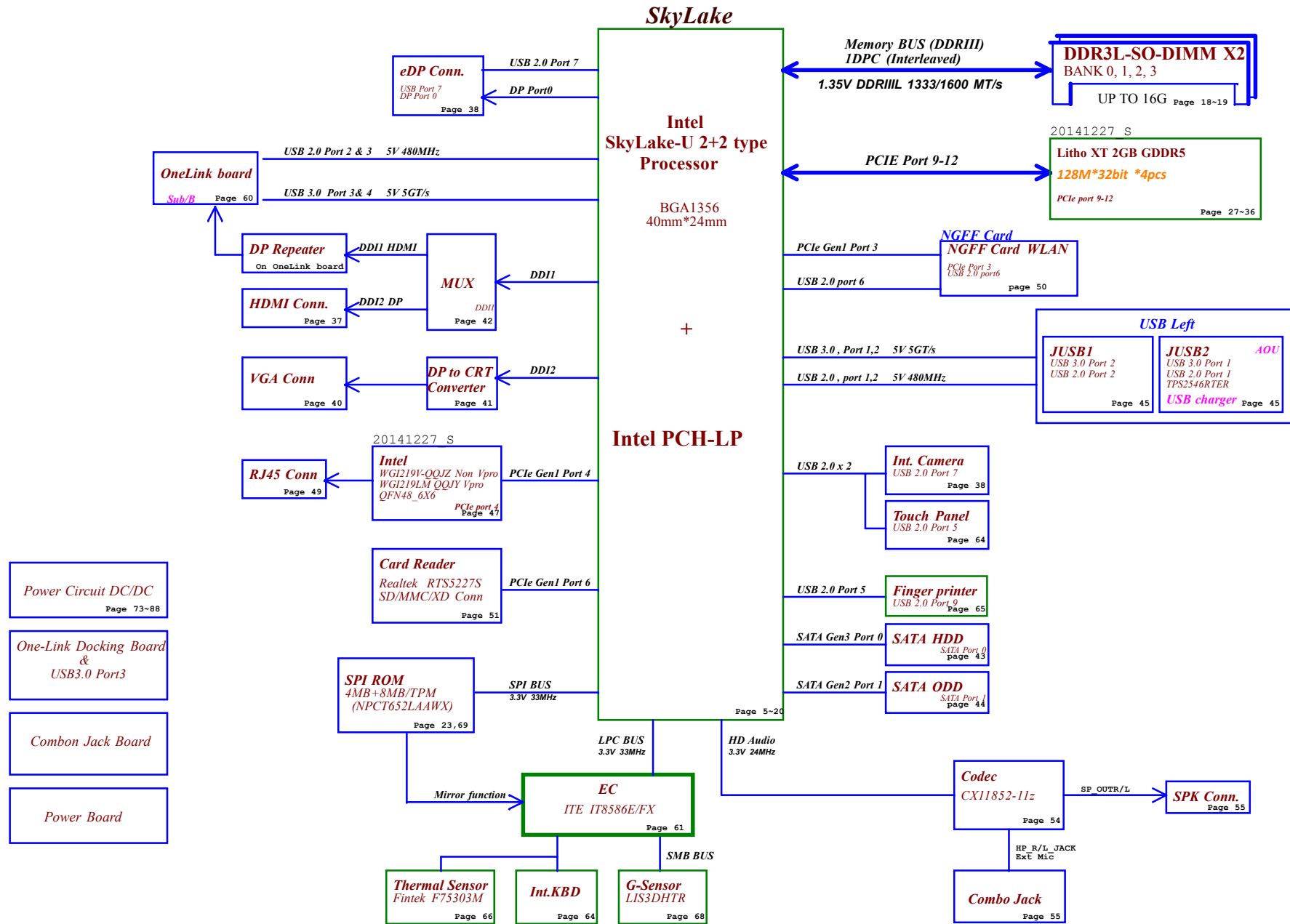
## ***BE560 Rev1.0 Schematic***

***Intel SkyLake Processor with DDRIII-L + PCH-LP***

***AMD Litho XT GDDR5 2GB***

***2015-07-28 Rev1.0***

Security Classification		LC Future Center Secret Data		Title	
Issued Date		Deciphered Date		COVER PAGE	
2013/11/04		2014/09/07			
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Size		Document Number		Rev	
Custom		BE560		0.1	
Date: Wednesday, September 23, 2015 1 Sheet of 99					



Voltage Rails ( O --> Means ON , X --> Means OFF )

Power Plane / State	B+	+3VALW +5VALW +1.8VALW +1VALW	+1.35V	+5VS +3VS +VCC_CORE +VCC_IO +VCC_SA +VCC_ST +VCC_STG +VGA_CORE +3VS_VGA +1.8VS_VGA +1.35VS_VGA +0.675VS
S0	O	O	O	O
S3	O	O	O	X
S5 S4/AC Only	O	O	X	X
S5 S4 Battery only	O	X	X	X
S5 S4 AC & Battery don't exist	X	X	X	X

STATE \ SIGNAL	SLP_A#	SLP_S3#	SLP_S4#	SLP_S5#	EC_ON2	EC_ON	SUSP#
Full ON	HIGH	HIGH	HIGH	HIGH	ON	ON	ON
S1 (Power On Suspend)	HIGH	HIGH	HIGH	HIGH	ON	ON	ON
S3 (Suspend to RAM)	LOW	LOW	HIGH	HIGH	ON	ON	OFF
S4 (Suspend to Disk)	LOW	LOW	LOW	HIGH	ON	ON	OFF
S5 (Soft OFF)	LOW	LOW	LOW	LOW	ON	ON	OFF

SMBUS Control Table

	SOURCE	Main VGA	BATT	SODIMM	WLAN WiMAX	Thermal Sensor	PCH	CP Module	Security ROM	LAN PHY	G sensor
EC_SMB_CK1 EC_SMB_DA1	IT8580F +3VL	X	V +3VALW	X	X	X	X	X	X	X	X
EC_SMB_CK3 EC_SMB_DA3	IT8580F +3VS	V +3VS_VGA	X	X	X	V +3VS	V +3V_PCH	X	X	X	V +3VALW_GS
PCH_SMB_CLK PCH_SMB_DATA	PCH +3V_PCH	X	X	V +3VS	X	X	X	V +5VS	V +3VS	X	X
PCH_SML0_CLK PCH_SML0_DAT	PCH +3V_PCH	X	X	X	X	X	X	X	X	V +3VALW	X

USB2 Port

Port	Device
1	JUSB2
2	JUSB3
3	Sub Board
4	Docking
5	Touch Panel
6	BT
7	CMOS
8	FP/Smart

USB3 Port

Port	Device
1	JUSB2
2	JUSB3
3	Sub Board
4	Docking
5	3D CCD (PCIE1)

PCIE Port

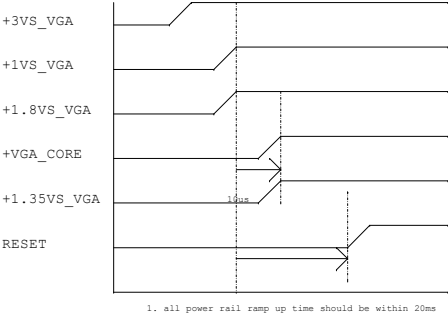
Port	Device
1	3D CCD (USB3)
2	X
3	WLAN
4	LAN
5	X
6	CardReader
7	X
8	X
9	GPU
10	GPU
11	GPU
12	GPU

SATA Port

Port	Device
1	HDD
2	ODD
3	X
4	X

VGA and DDR3 Voltage Rails (Litho XT 2GB DDR3) 20141227\_S

GPIO	I/O	ACTIVE	Function Description
GPIO0	OUT	N/A	
GPIO5	IN	-	GPIO5_AC_BATT
GPIO6	IN	-	GPIO6
GPIO7	OUT	N/A	
GPIO8	OUT	-	GPIO8_ROMSO
GPIO9	OUT	-	GPIO9_ROMSI
GPIO10	OUT	-	GPIO10_ROMSCK
GPIO11	OUT	N/A	
GPIO12	OUT	N/A	
GPIO13	OUT	N/A	
GPIO15	IN	N/A	SVI2_SVD
GPIO16	OUT	N/A	
GPIO17	OUT	N/A	
GPIO19	OUT	N/A	GPIO19_CTF
GPIO20	IN	IN	GPIO20
GPIO21	OUT	N/A	
GPIO22	OUT	N/A	GPIO22_ROMCSB
GPIO29	OUT	N/A	
GPIO30	OUT	N/A	



	Device ID		setting	I2C Slave addresses ID
JET-XT	0xFFFF	SMB_ALT_ADDR (ROM_SO Bit 1)	0	0xFF
			1	0xFF

**vinafix**

BOM Structure Table

BOM Structure	NOTE
PCB@	For PCB load BOM
XDP@	Debug port
UMA@	UMA SKU ID
DIS@	Optimus SKU ID
DIMM2@	For DIMM2 function
DIMM1@	For DIMM1 function
VPRO@	For VPRO function
ME@	ME Connector
EMC@	For EMC function
EMC_2D@	For EMC function
EMC_NS@	For EMC function
RF_NS@	For RF function
S2G@	For VRAM Strap
CHA@	For VRAMA function
CHB@	For VRAMB function
RANKA@	GPU DDR5 Setting
X76@	GPU VRAM Setting
3DCCD@	3D Camera Setting
VGA@	VGA Setting
MUX@	MUX Setting
ODD@	ODD Setting
TPM@	Trusted Platform Module (TPM)
NVPRO@	For Non-VPRO function
MIRROR@	For mirror function
.	

GPU		Litho XT 2GB DDR3	
FB Memory (DDR3L)		PS_3 (RV114)	PS_3 (RV117)
Samsung 1000MHz	K4W4G1646D-BC1A		
	256Mx16	PH 3.4K	PD 10K
Hynix 1000MHz	H5TC4G63AFR-11C		
	256Mx16	PH 4.75K	NC
Micro 1000MHz	MT41J256M16HA-093G		
	256Mx16	PH 3.24K	PD 5.62K



[SKL PDG] If THERMTRIP# goes active, the CPU is indicating an overheat condition, and the PCM will immediately transition to an S5 state. CPU\_GP can be used from external sensors for the thermal management.

[SKL PDG] PROC\_OPI\_RCOMP: Signal should be pulled down to ground with a resistance of 50 ohm  
[SKL PDG] PCH\_OPI\_RCOMP: Signal should be pulled down to ground with a resistance of 50 ohm  
\*1 %

[SKL PDG] On Package Interface Compensation (OPI) Guidelines  
Should be referenced to VSS plane only. VSS reference planes must be continuous  
Require low DC resistance routing <0.2 ohm  
Avoid routing next to clock pins or noisy signals.

[SKL PDG] Refer Figure 45-1

[SKL PDG] Refer Figure 45-1

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Issued Date	2014/05/07	Deciphered Date	2015/05/07	SKL(2/16):MISC/JTAG	
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Customer				AIVL2 NM-A351	
Date				Wednesday, September 23, 2015	
Sheet				6 of 99	

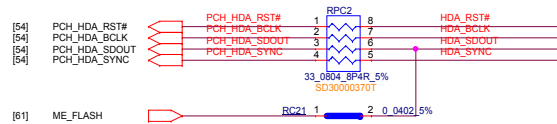






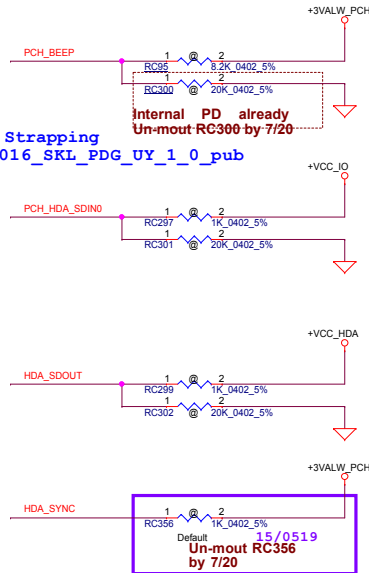
[SKL PDG] Manufacturing Mode Jumper

1. If strap is sampled low, the security measures defined in the Flash Descriptor will be in effect (default)  
2. If sampled high, the Flash Descriptor Security will be overridden.



GPP\_B14, Internal PD 20K  
No Reboot on TCO  
Timer expiration  
pull-up to VCC3\_3 through a 18.2 K 5% resistor to disable this capability

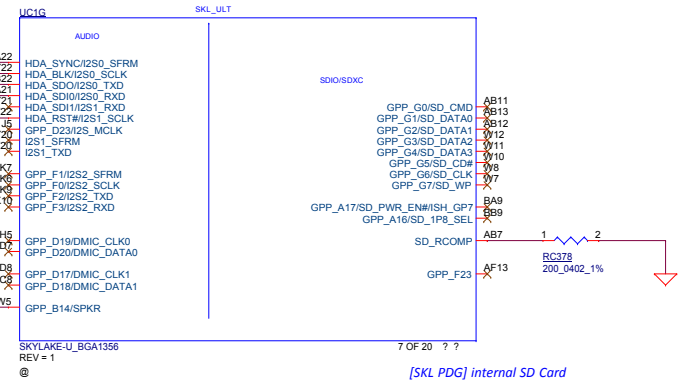
Processor Strapping  
543016\_543016\_SKL\_PDG\_UY\_1\_0\_pub  
P780



Check RC377 to remove  
by 7/20

[54] PCH\_HDA\_SDOIN0

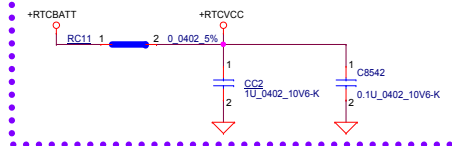
[55] PCH\_BEOP



[SKL PDG] internal SD Card

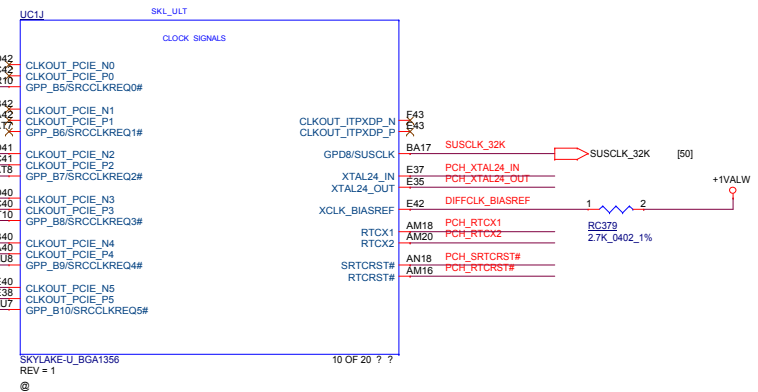
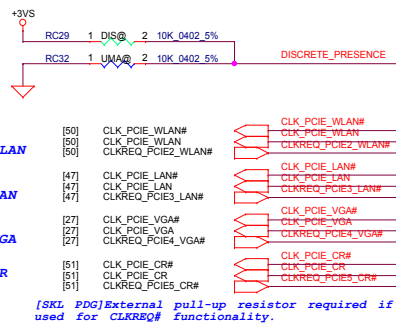
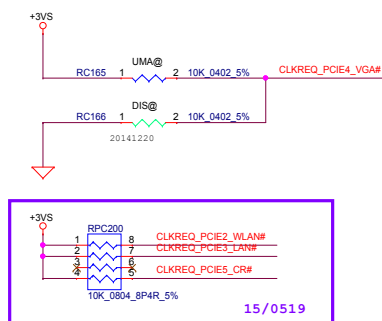
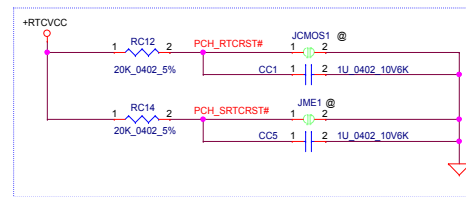
20150514

## RTC External Circuit



+RTCBATT, +RTCVCC  
Trace width = 20mils

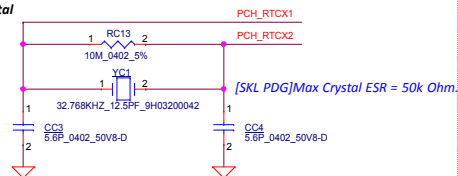
JCMOS, JME Setting, Need Under DDR Door



[SKL PDG]Used to set BIAS reference for differential clocks. Connect to a [RC379] 2.71K  $\pm$  0.5% precision resistor to 1.0v.

- [SKL PDG]
- 1.Space > 15mils
  - 2.No trace under crystal
  - 3.Place on opposit side of MCP for temp inf l uence
  - 4.The exact capacitor values forC1 and C2 must be based on the crystal maker recommendat ions
- Typical values for C1 and C2 are 18 pF, based on crystal load of 12.5 pF.

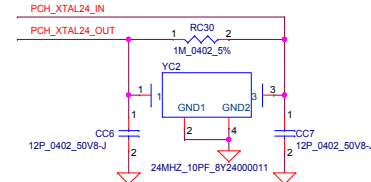
## RTC Crystal



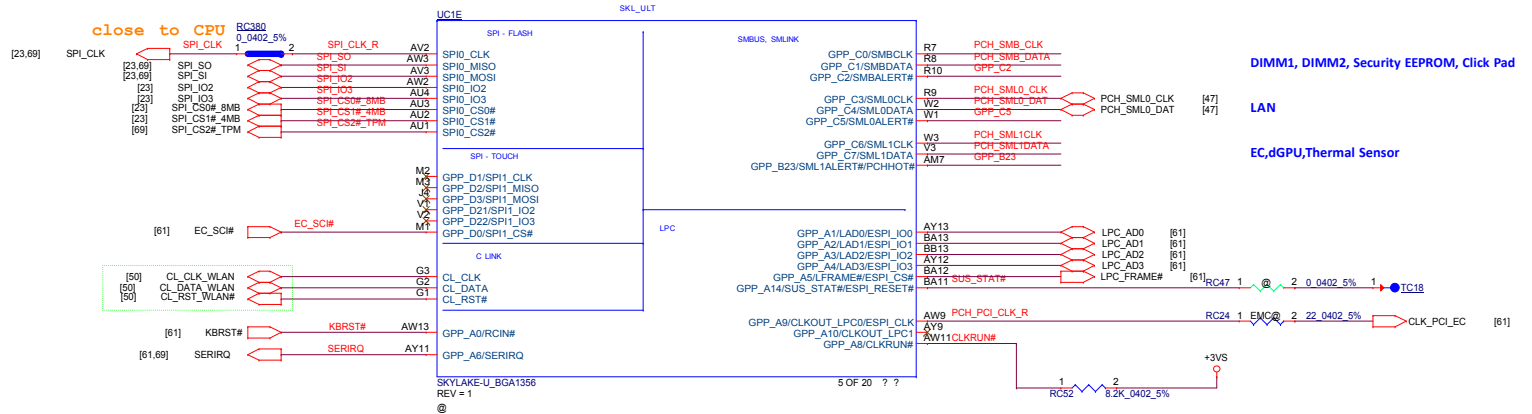
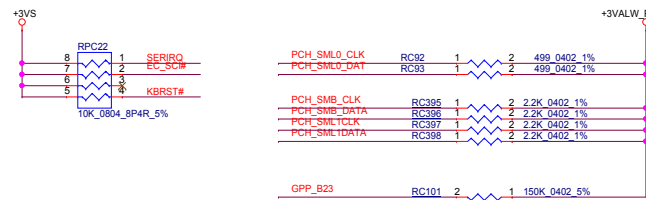
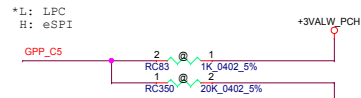
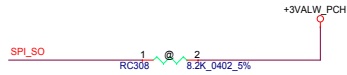
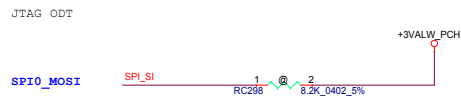
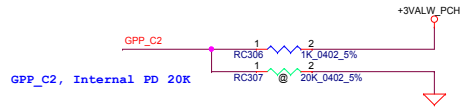
[SKL PDG]Max Crystal ESR = 50k Ohm.

[SKL PDG]

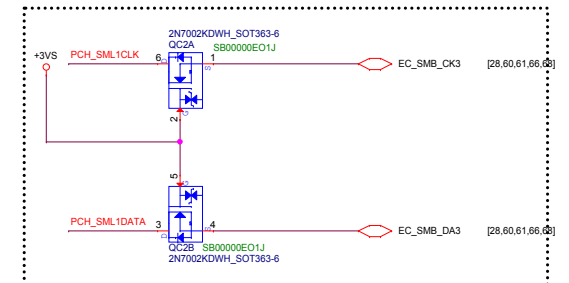
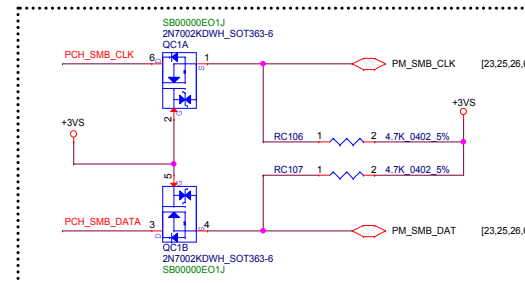
- 1.A 24 MHz crystal with crystal frequency tolerance and stability of +/-30 ppm
- 2.Two External Load Capacitors (Ce1 and Ce2)
- 3.A 1-Mohm bias resistor (Rf)




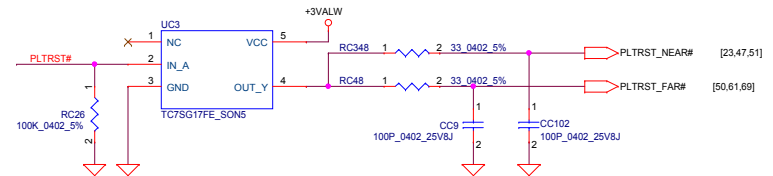
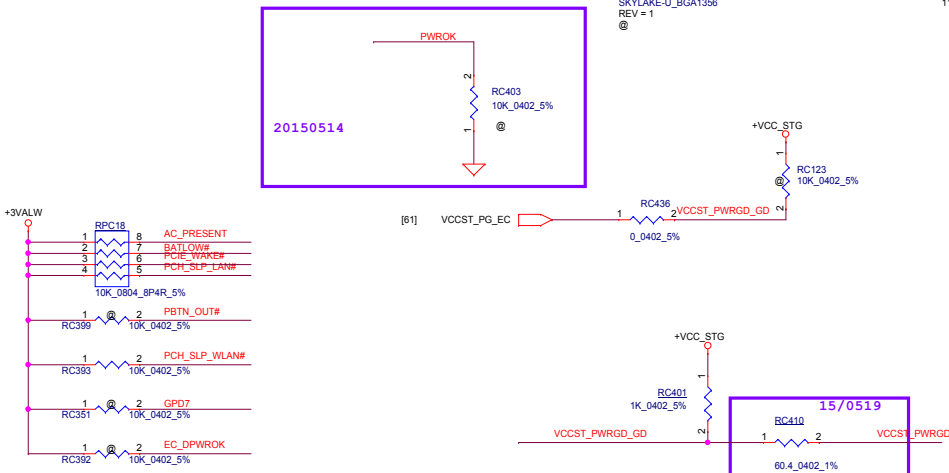
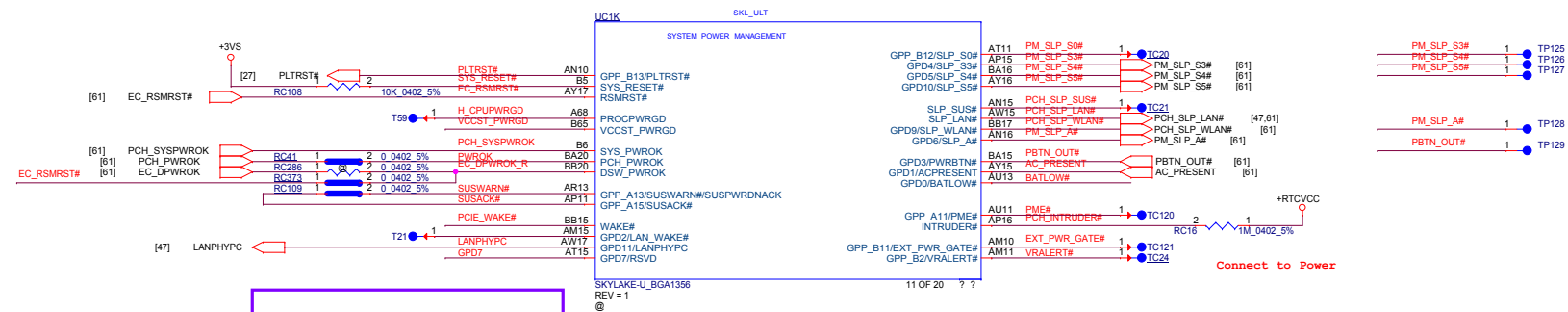
```
L:Disable Intel ME Crypto TLS cipher suite (no confidentiality).
*:Enable Intel ME Crypto Transport Layer Security (TLS) cipher
suite (with confidentiality).Support Intel AMT with TLS and Intel
SBA (Small Business Advantage) with TLS.
```

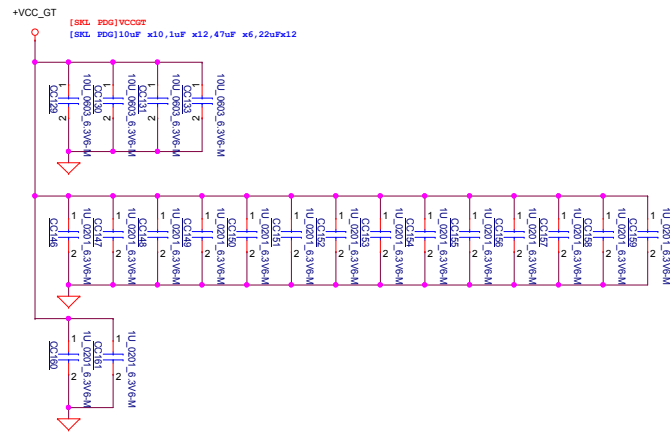
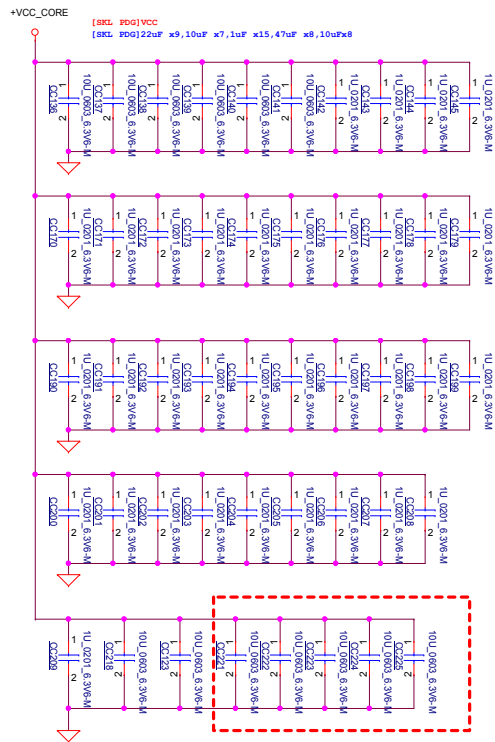


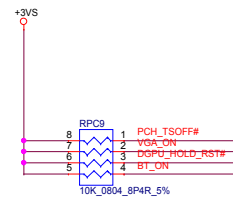
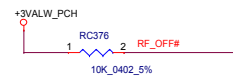
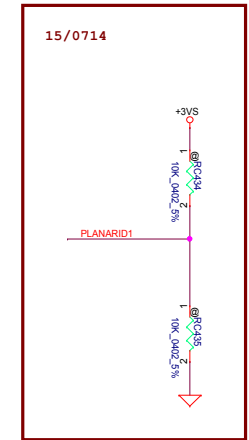
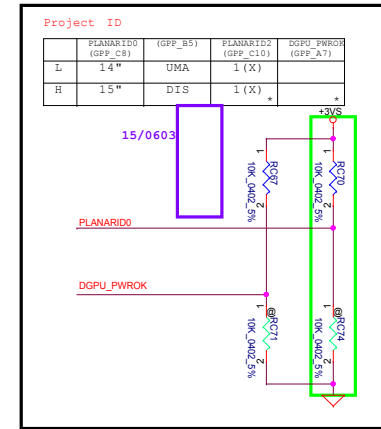
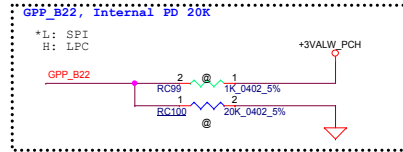
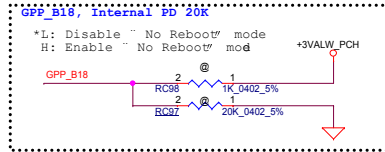
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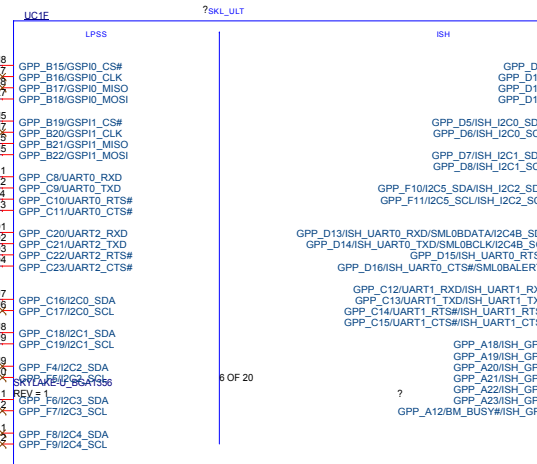
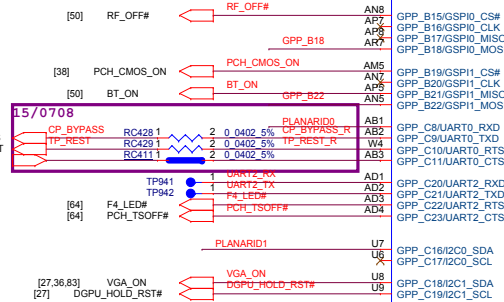
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Issued Date	2014/05/07	Deciphered Date	2015/05/07	SKL(7/16):LPC/SPI/SMBUS/CL		
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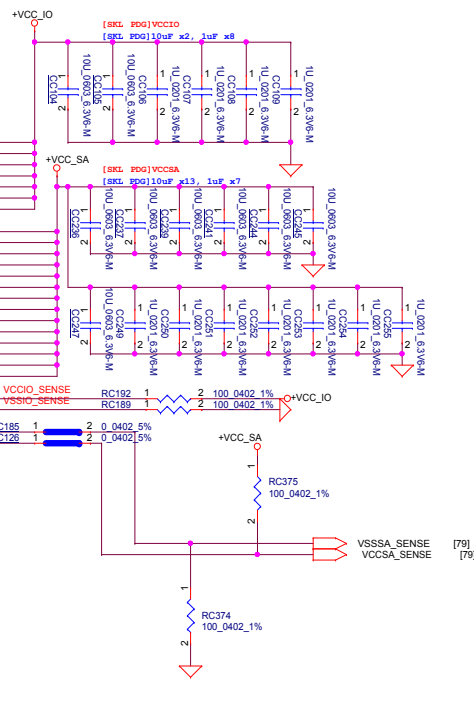
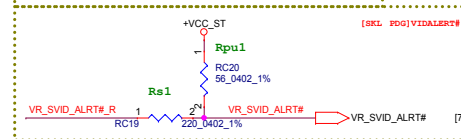
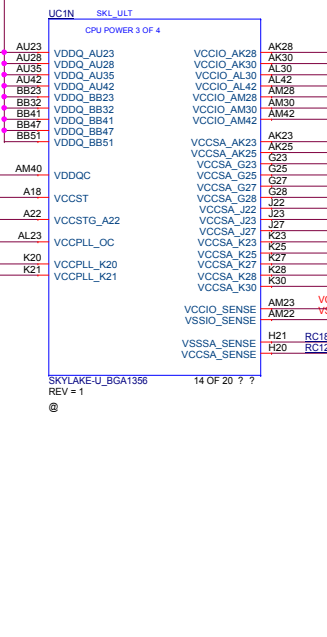
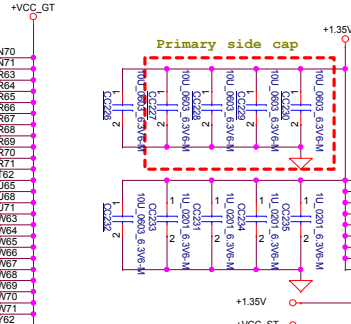
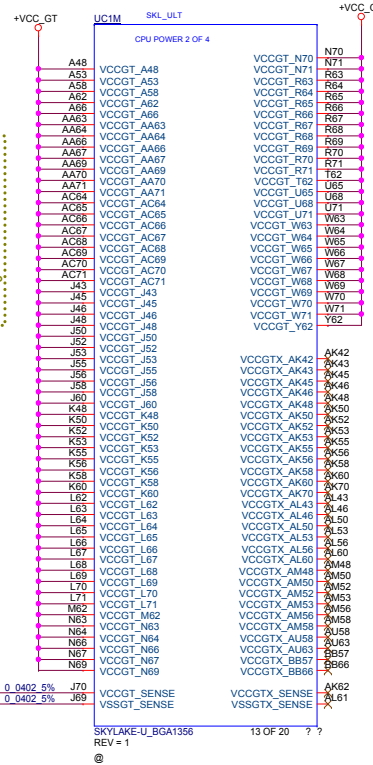




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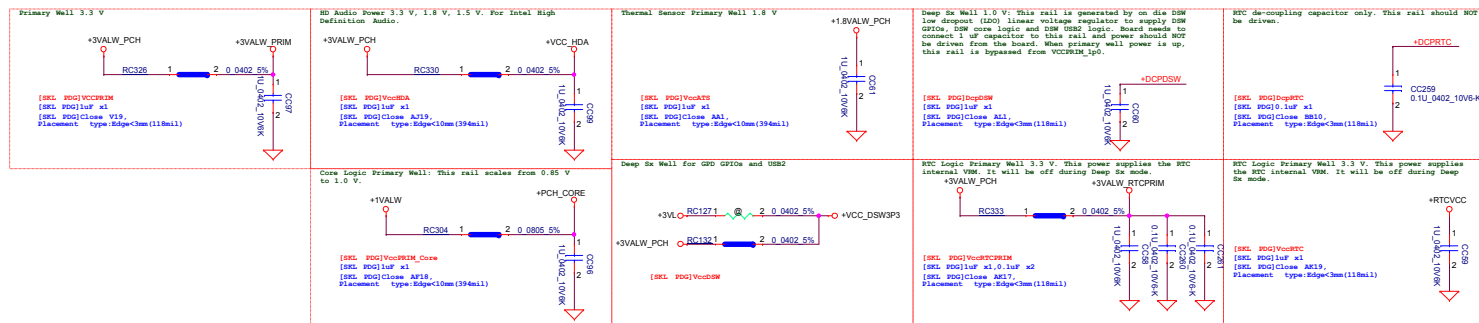
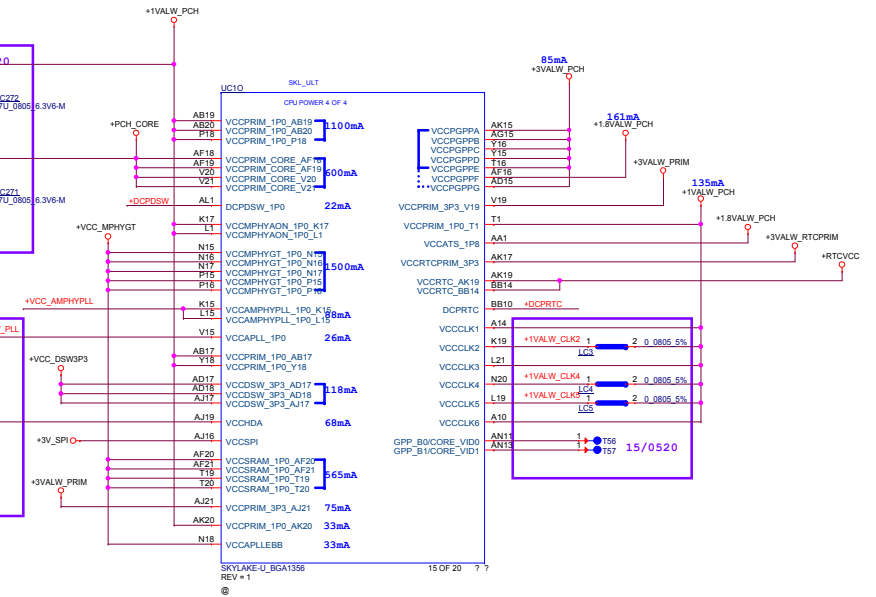
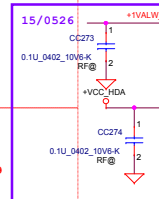
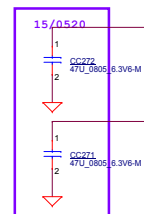
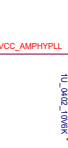





Signal	W1 [inches]	W2 [inches]	W3/4/5 [inches]	W2+W3+W4+W5 [inches]	W51 [inches]	W52 [inches]	R <sub>P11</sub> [Ω]	R <sub>P12</sub> [Ω]	R <sub>S1</sub> [Ω]	R <sub>S2</sub> [Ω]	VCC <sub>ST</sub> [v]
VIDSOUT	0.5-3	1-15	0.5-4	3-17	<0.1	<0.1	100	100	0	10	1.0
VIDSCK							Empty	45	0	50	
VIDALERT #							56	Empt y	220	0	

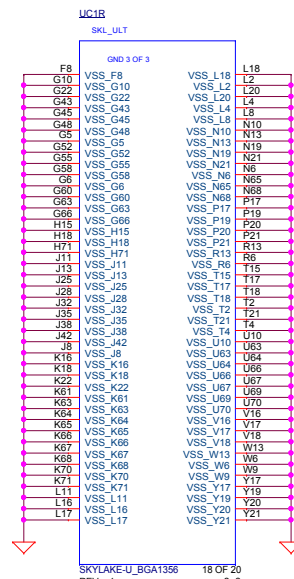
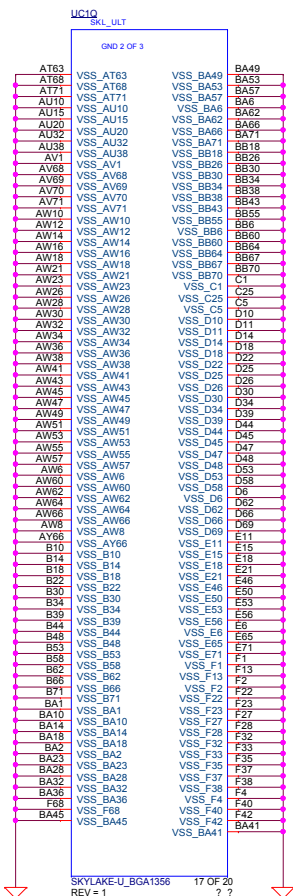
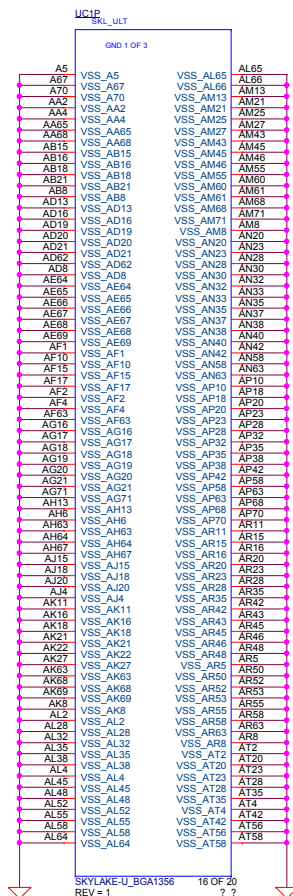
Signal	W1 [inches]	W2 [inches]	W3/4/5 [inches]	W2+W3+W4+W5 [inches]	W51 [inches]	W52 [inches]	R <sub>P11</sub> [Ω]	R <sub>P12</sub> [Ω]	R <sub>S1</sub> [Ω]	R <sub>S2</sub> [Ω]	VCC <sub>ST</sub> [v]
VIDSOUT	0.5-3	1-15	0.5-4	3-17	<0.1	<0.1	100	100	0	10	1.0
VIDSCK							Empty	45	0	50	
VIDALERT #							56	Empt y	220	0	

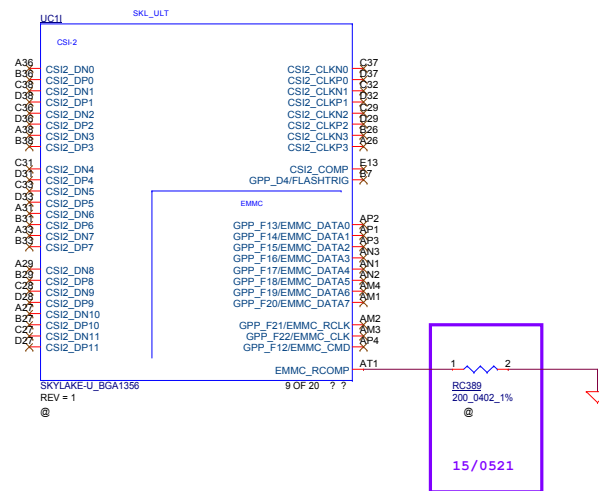




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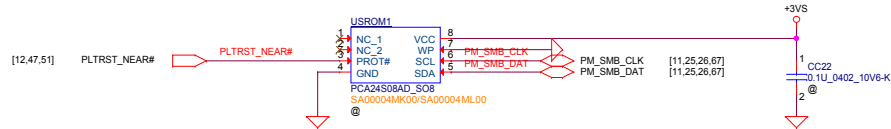
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Issued Date	2014/05/07	Deciphered Date	2015/05/07	SKL(13/16):POWER			
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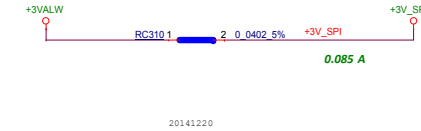




## Security ROM



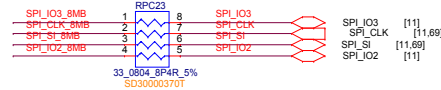
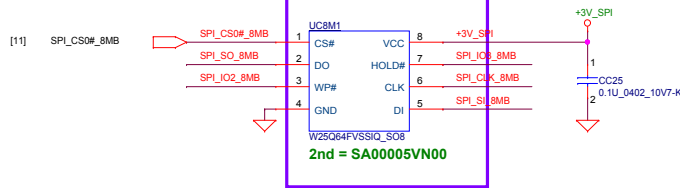
## M3 Support + Intel LAN PHY / Wireless LAN Solution



[SK1]SPI0\_CS0#: SPI FLASH  
SPI0\_CS1#: SPI FLASH  
SPI0\_CS2#: SPI TPM

8MB(64Mb)

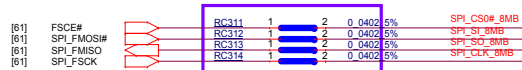
feedback to SDV rev..  
15/0522



### Near SPI ROM

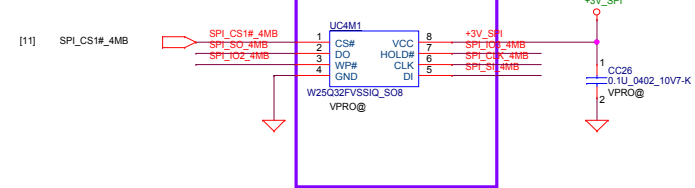


### Mirror Code



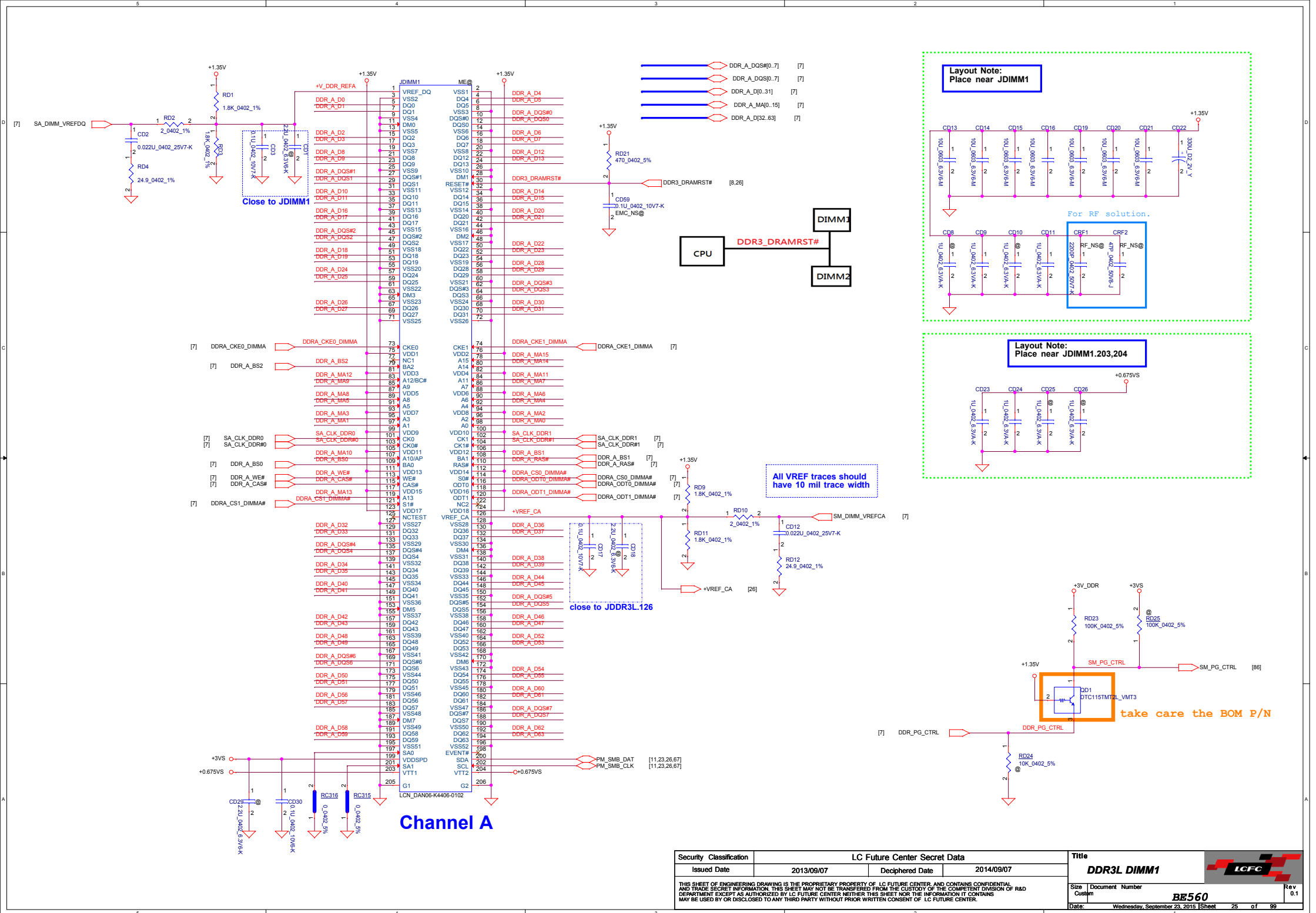
Close to SPI ROM (UC8M1).

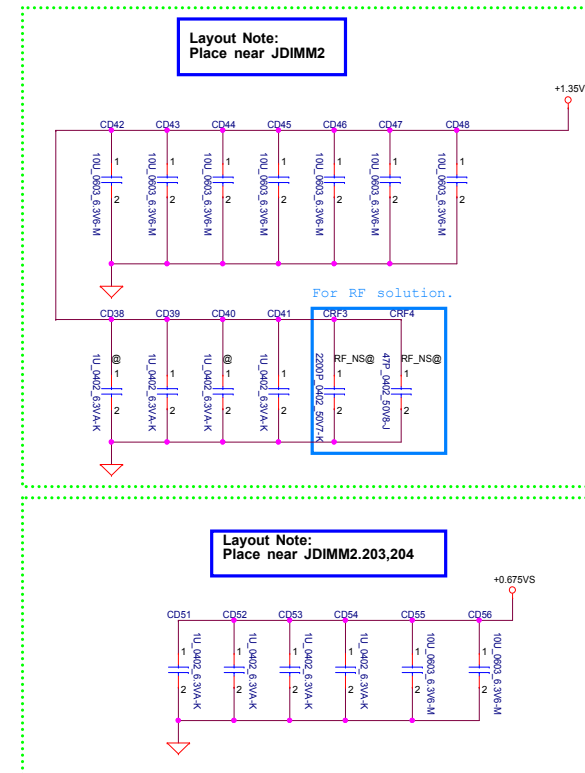
## 4MB(32Mb) for VPRO SKU




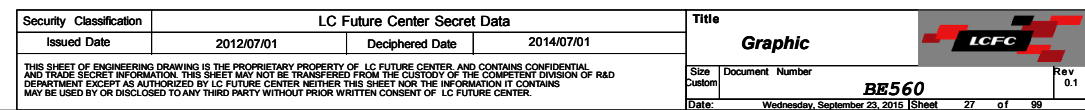
### Near SPI ROM



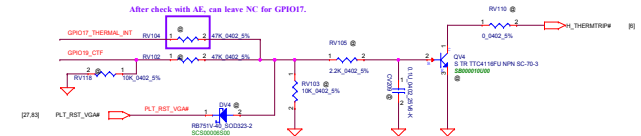
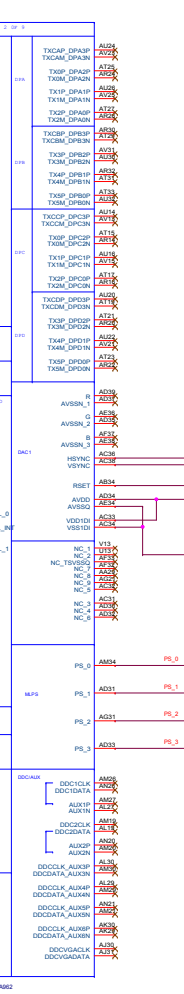
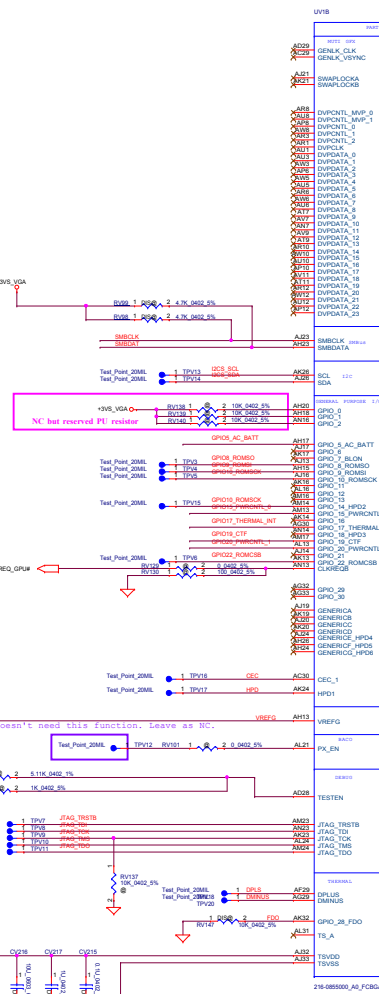
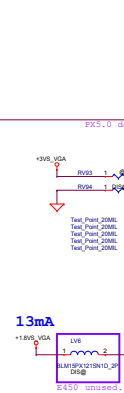
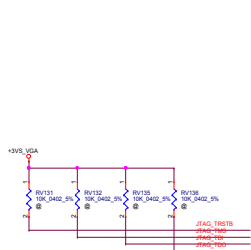
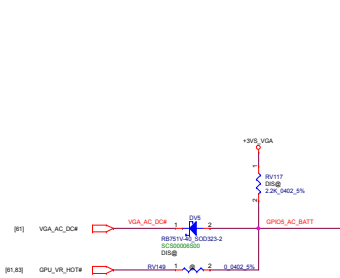
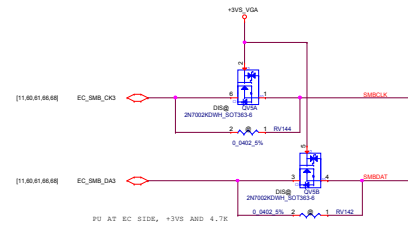




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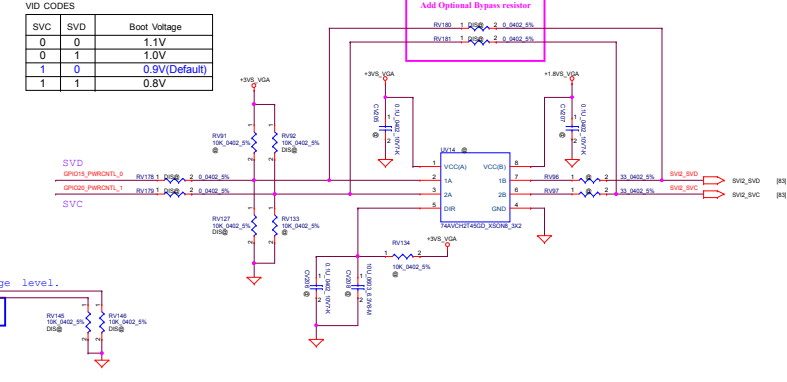






VID CODES

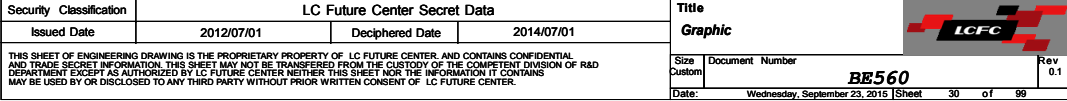
SVC	SVD	Boot Voltage
0	0	1.1V
0	1	1.0V
1	0	0.9V(Default)
1	1	0.8V

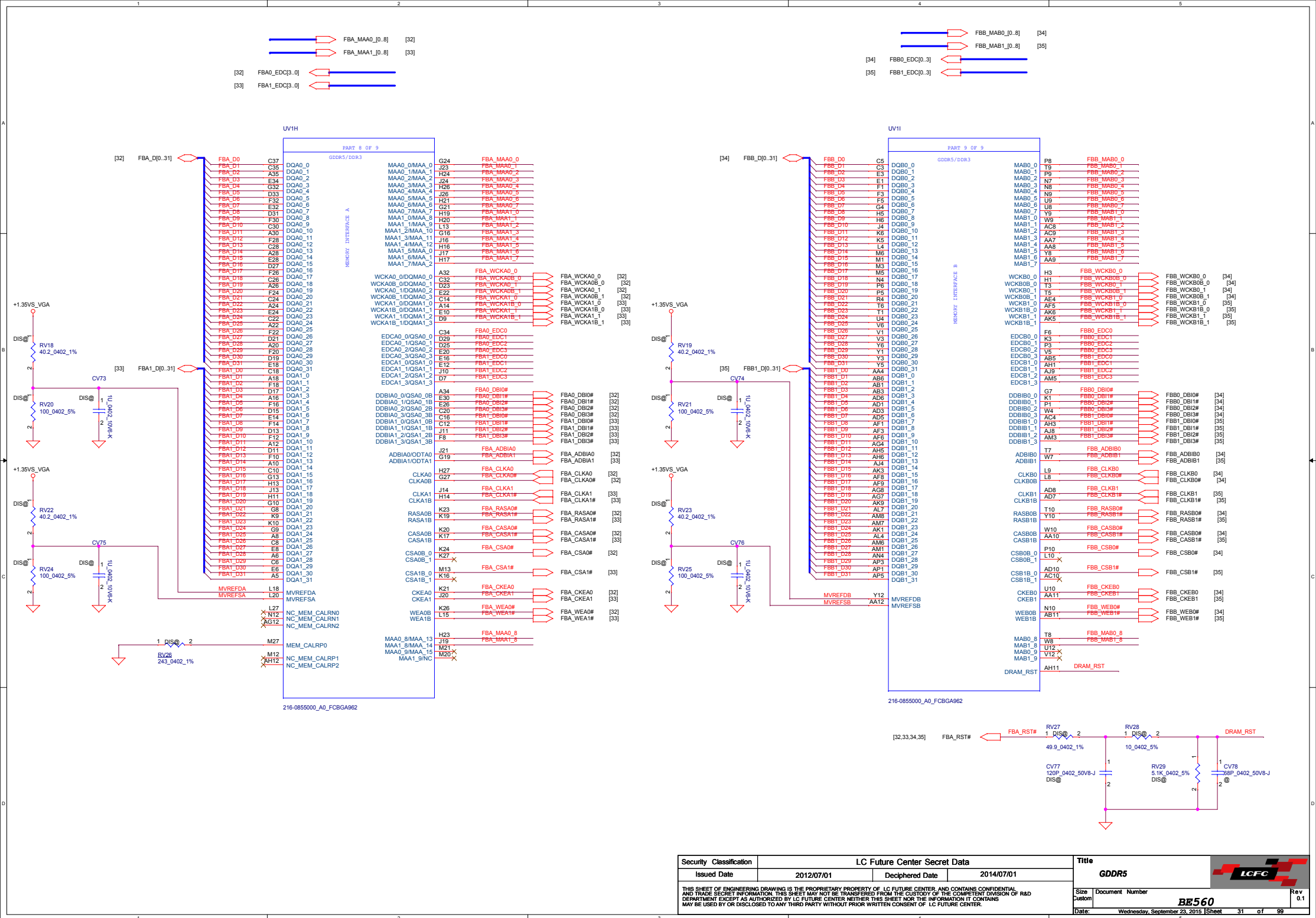


MLPS	Recommend setting	Value
PS_0	PS0[5..1] = 11001	RV112 = 8.45K ohm RV113 = 2K ohm CV213 = NC
PS_1	PS1[5..1] = 11000	RV106 = NC RV109 = 4.75K ohm CV212 = NC
PS_2	PS2[5..1] = 11000	RV108 = NC RV111 = 4.75K ohm CV210 = NC
PS_3	PS3[5..1] = 11xx	RV114 = RV107 = CV211 = NC

	RV114	RV107	Strap PS_3[3..1]
FB Memory (DDR3L)			
Samung	1G	PU 6.45K	PD 2K
	2G	PU 3.4K	PD 10K
Rynix	1G	PU 4.53K	PD 2K
	2G	PU 4.75K	PD 11K
Micron	1G	NC	PD 4.75K
	2G	PU 3.24K	PD 5.62K

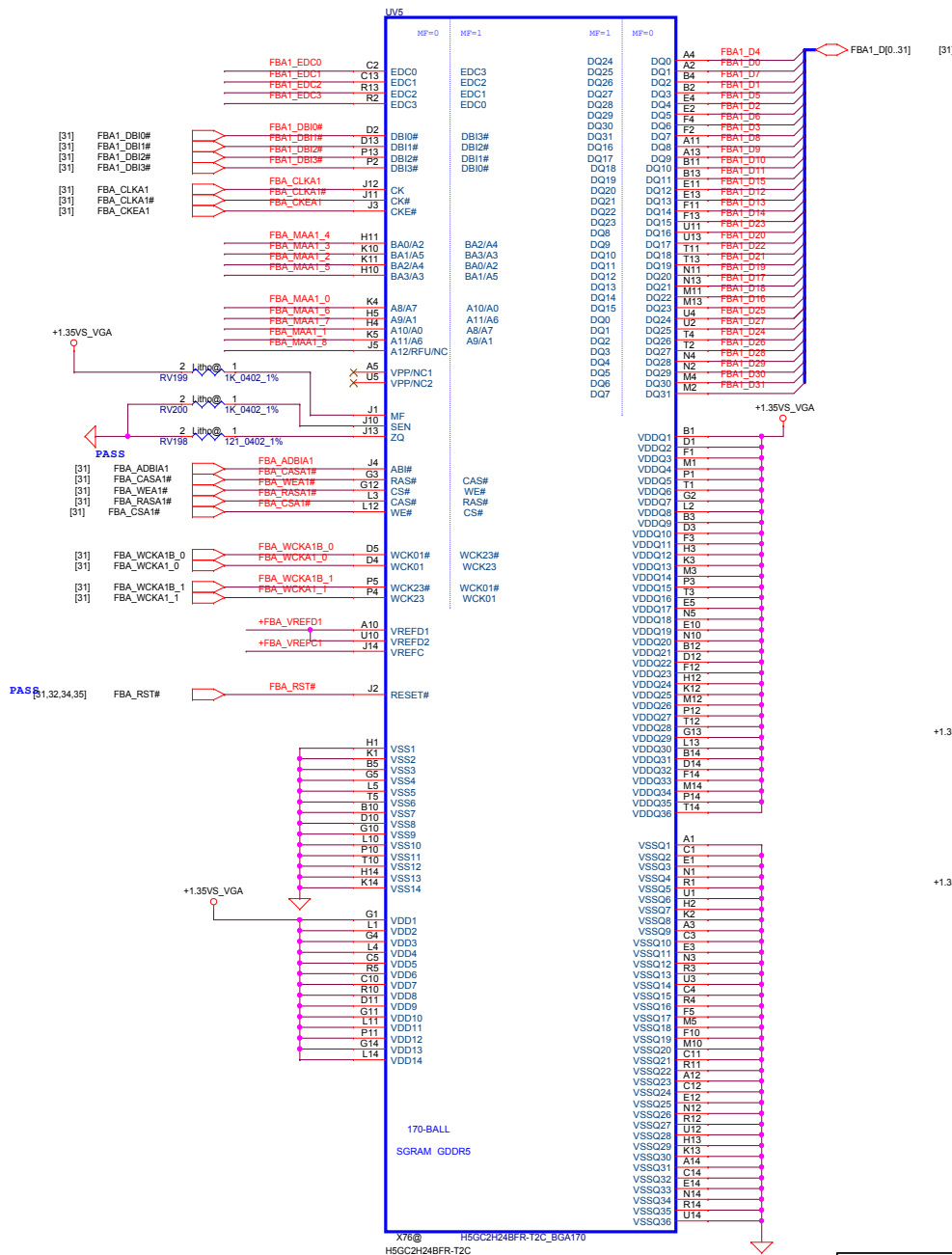




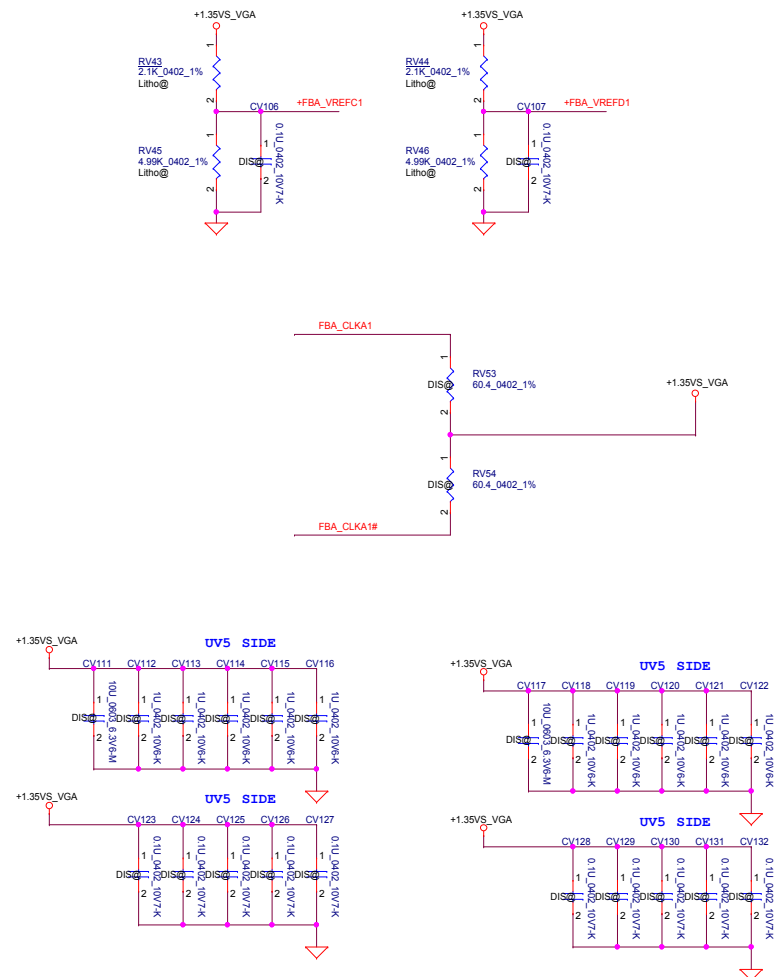





# Memory Partition A - Upper 32 bits

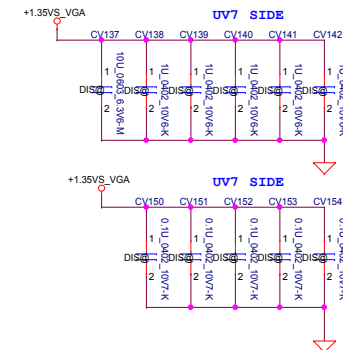
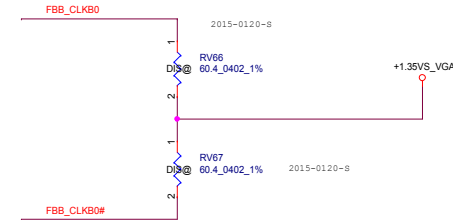
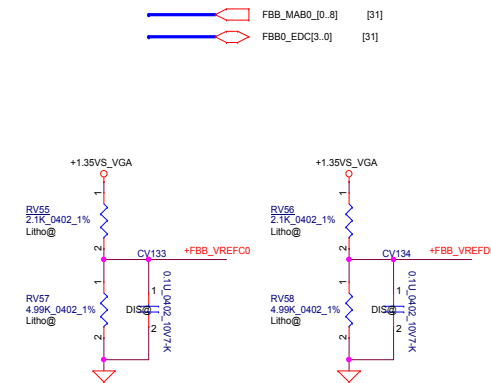
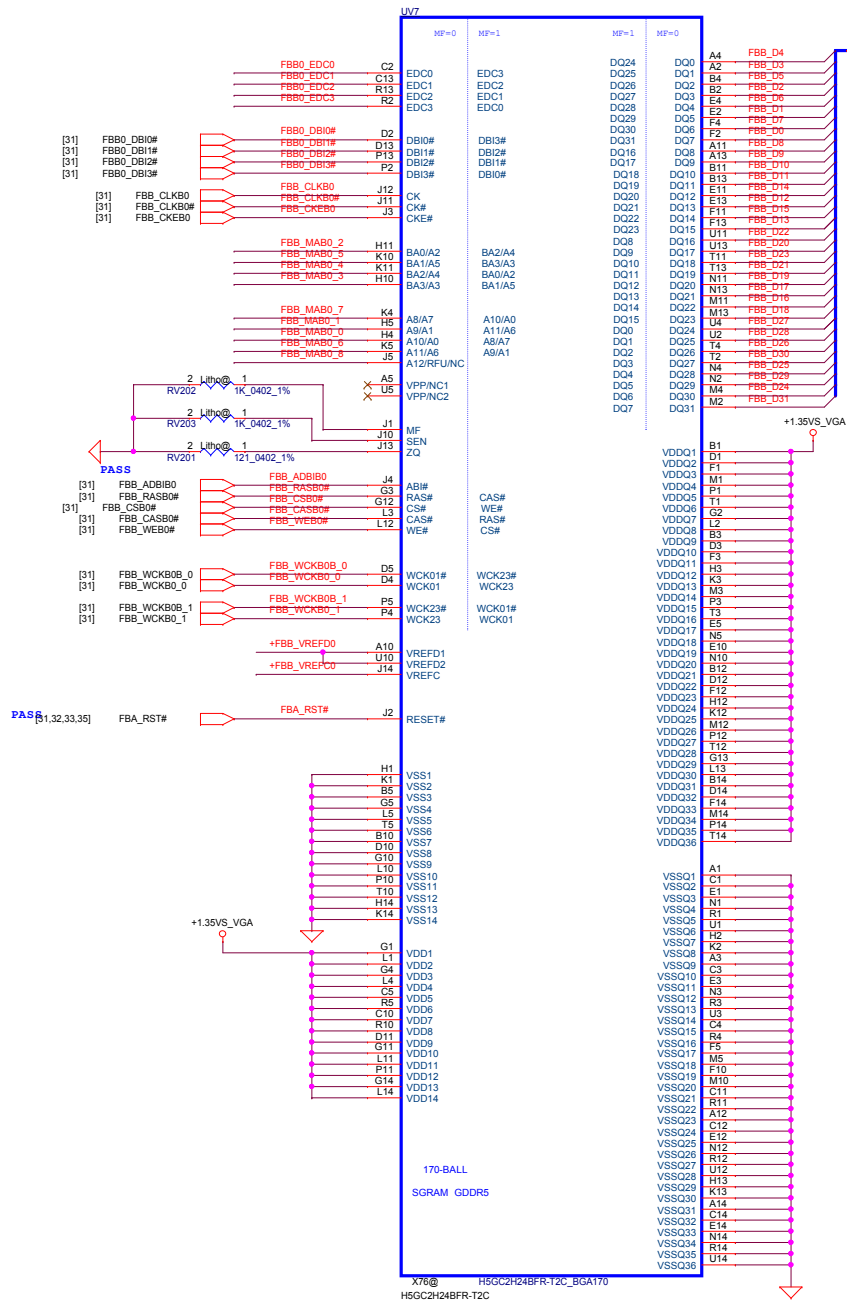



FBA\_MAA1[0..8] [31]  
FBA1\_EDC[3..0] [31]



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				Date:	Wednesday, September 23, 2015	Sheet 33 of 99

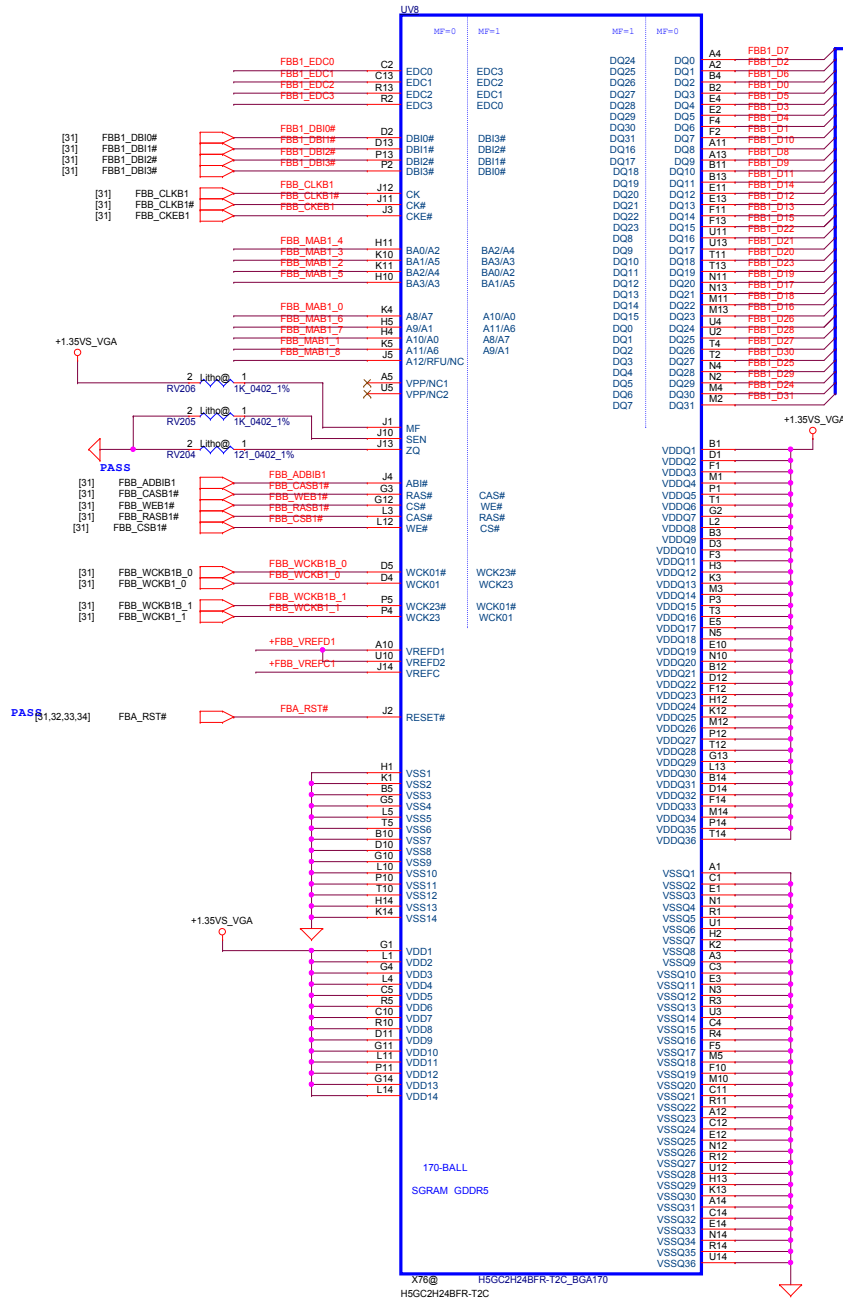
# Memory Partition A - Lower 32 bits



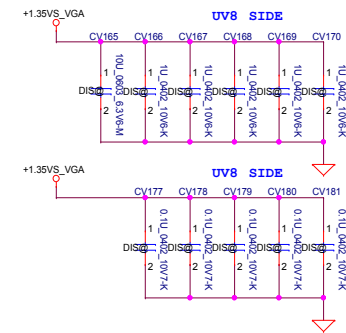
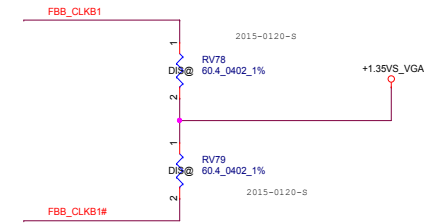
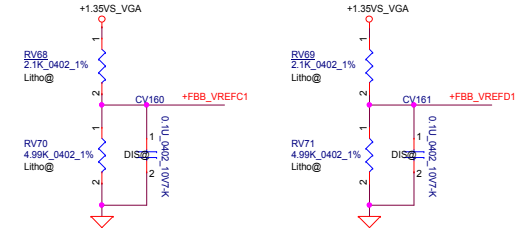
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				Document Number	
				BE560	
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				Rev 0.1	




# Memory Partition A - Upper 32 bits



FBB1\_MAB1\_0..8 [31]  
FBB1\_EDC3..0 [31]

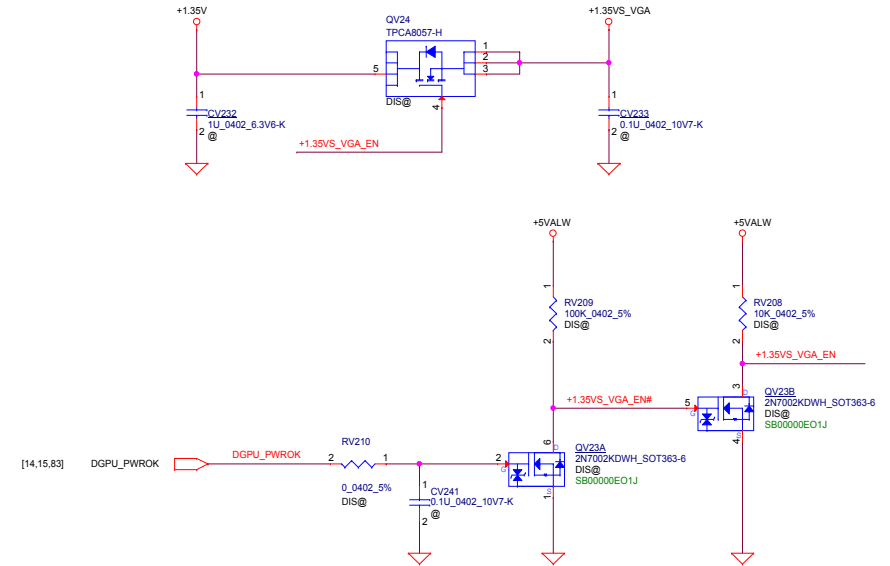
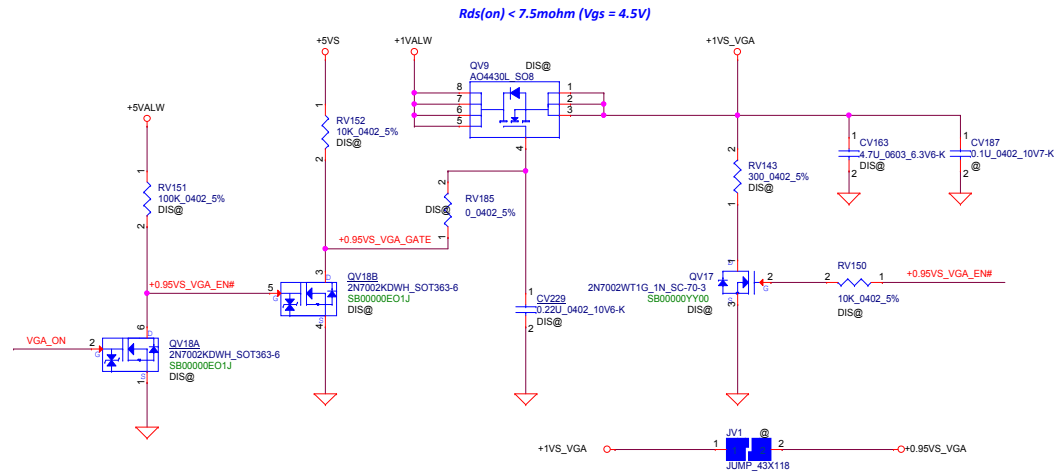


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				Customer	
				Rev	
				BE560	
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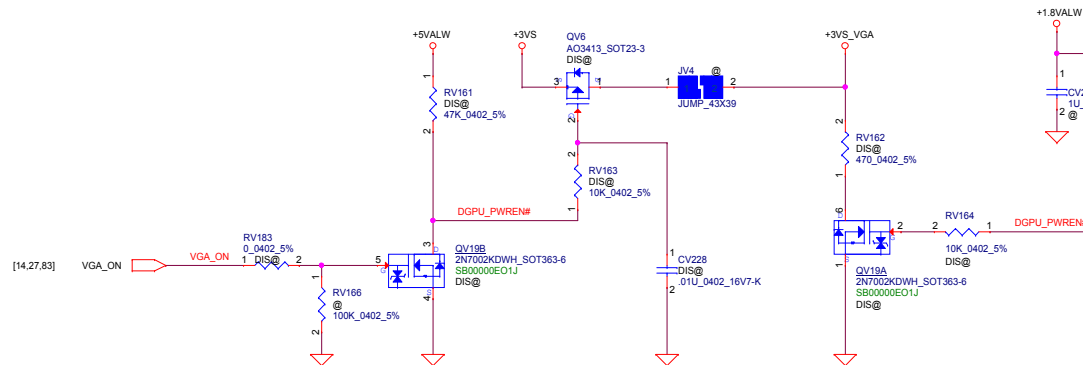


**+1.35V to +1.35VS\_VGA**

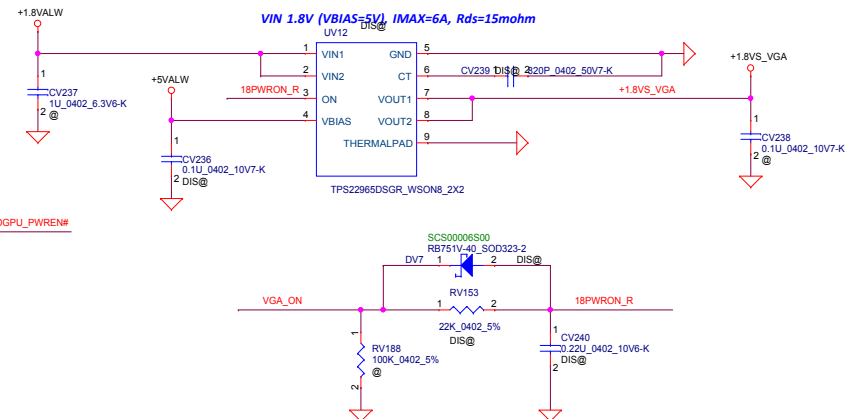
**+1.0VALW to +0.95VS\_VGA**



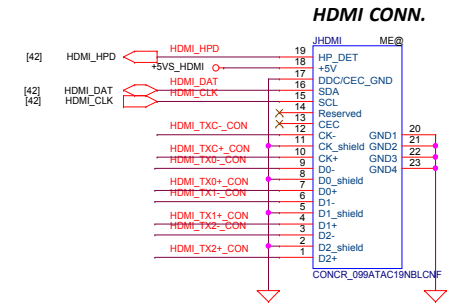
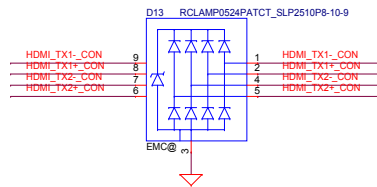
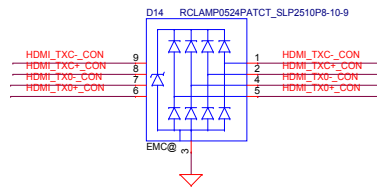
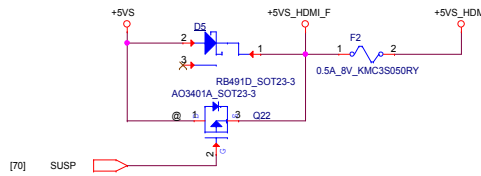
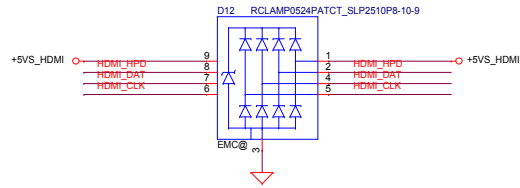
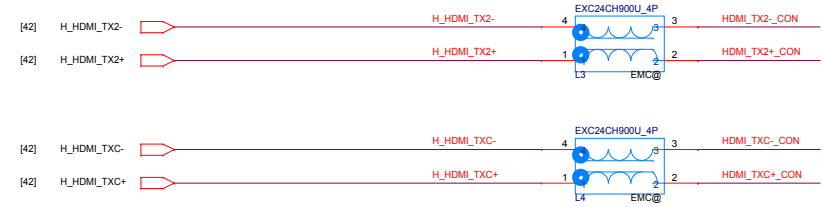
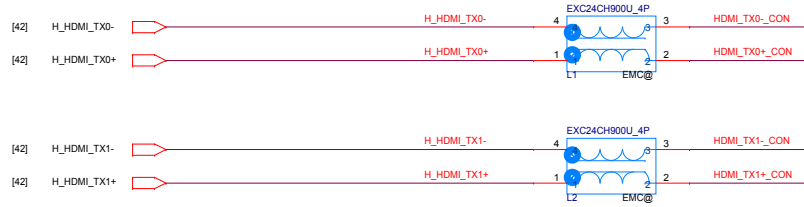
**+3VS to +3VS\_VGA**



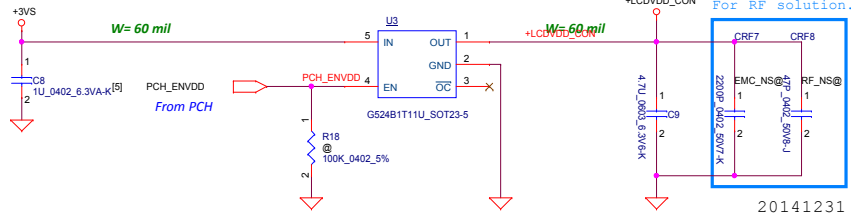
**+1.8VALW to +1.8VS\_VGA**



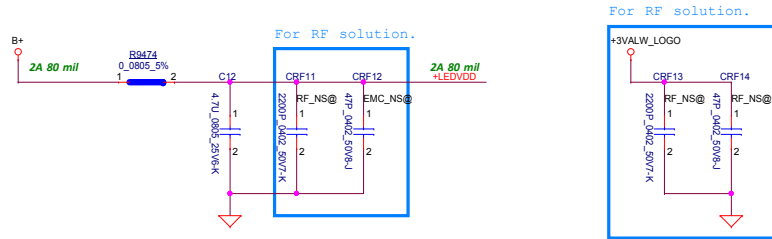
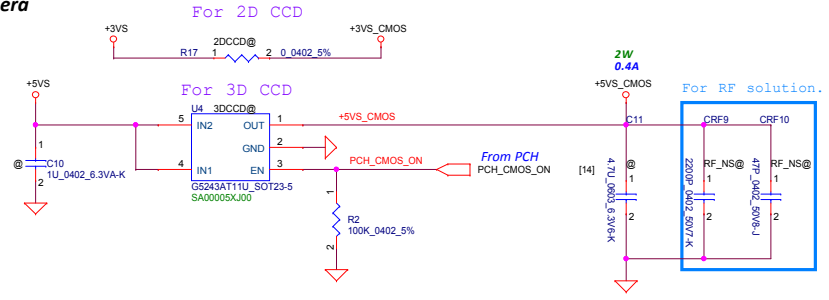
MLPS	Bit				
	5	4	3	2	1
PS_0[5:1]	1	1	0	0	1
PS_1[5:1]	1	1	0	0	0
PS_2[5:1]	1	1	0	0	0
PS_3[5:1]	1	1	X	X	X



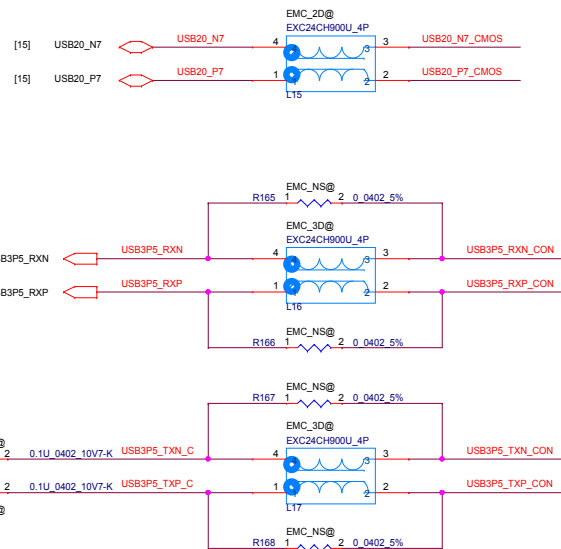
# LCDVDD Circuit



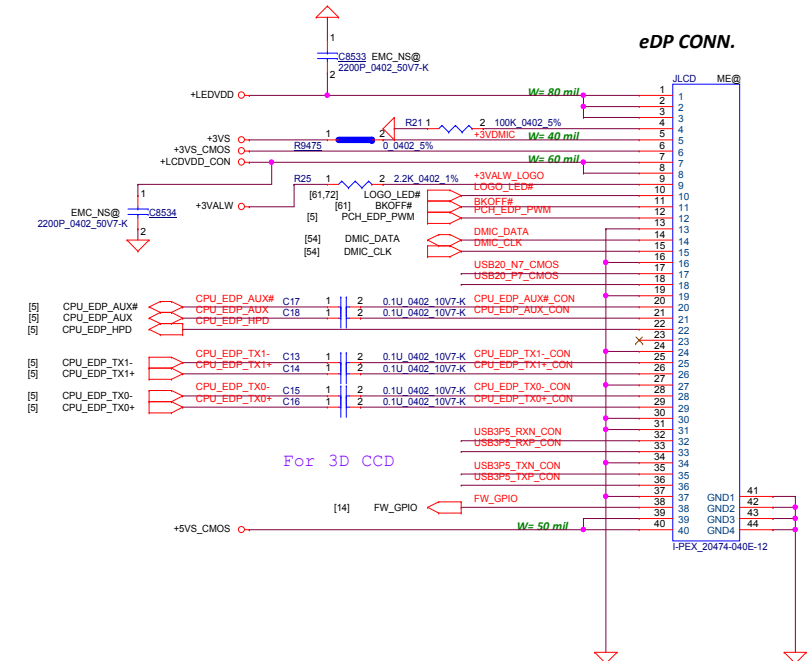
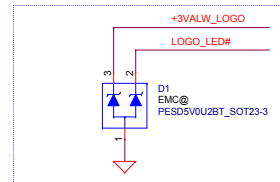
# CMOS Camera




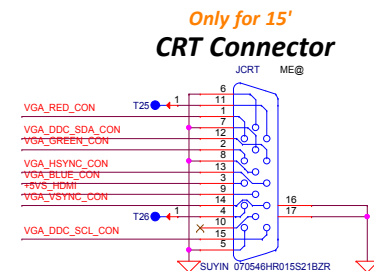
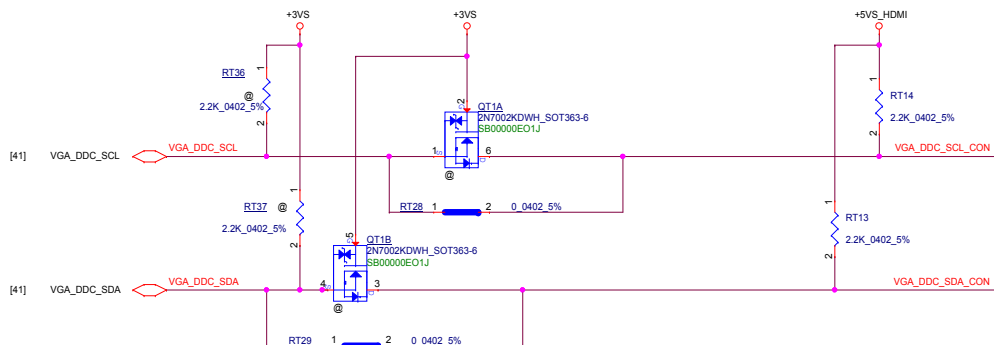
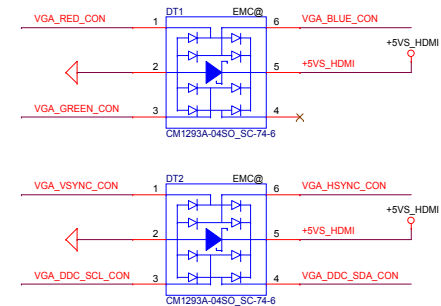
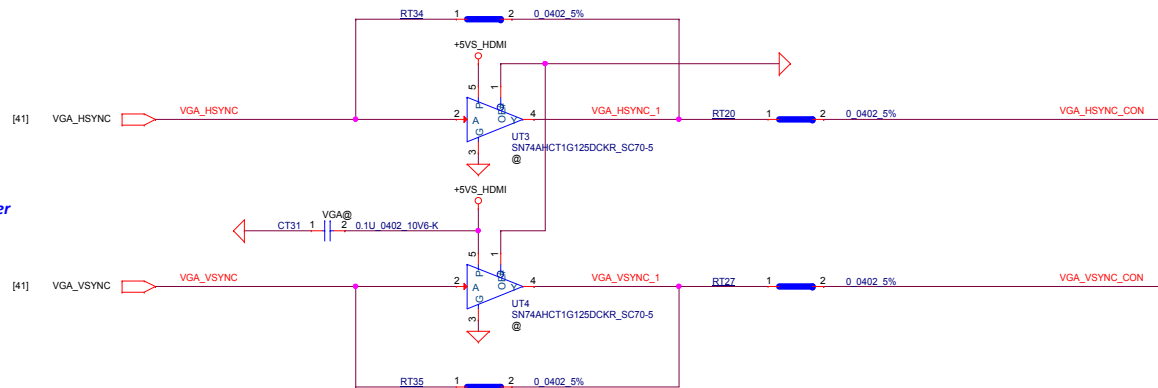
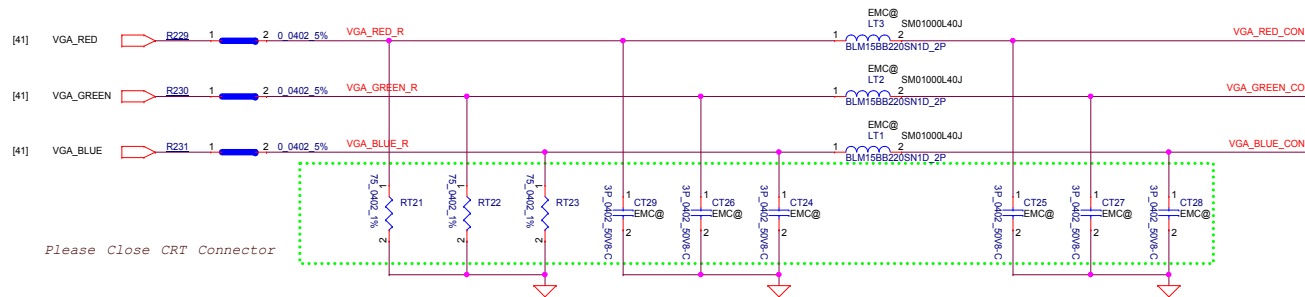
# CMOS USB Port 2



# ESD request



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				Date:			



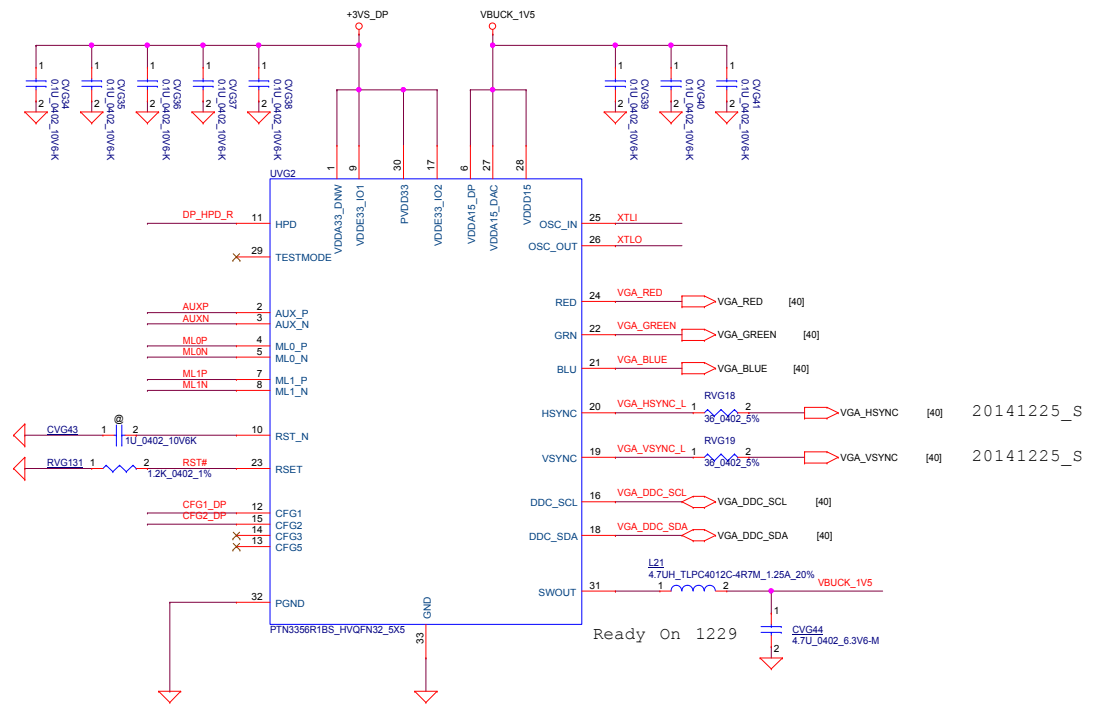
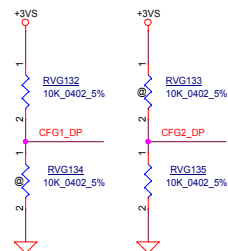
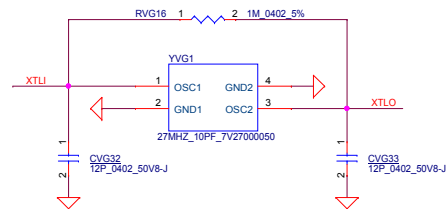
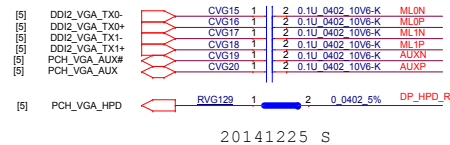
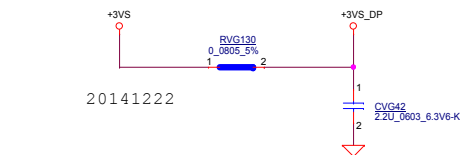


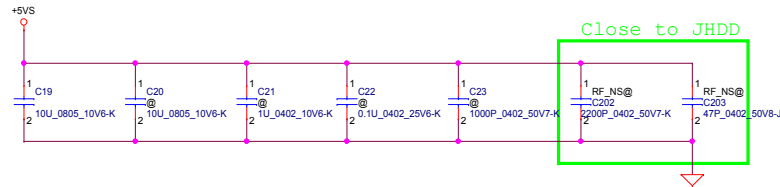
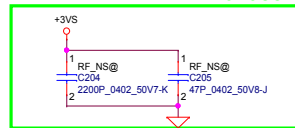
Table 7. CFG1/CFG2 pin definitions

Pin value	System behavior
00	Compliant HPD behavior
01	Most interoperable (non-compliant) HPD behavior
10	Most interoperable (non-compliant) HPD behavior
11	(Default) Compliant behavior



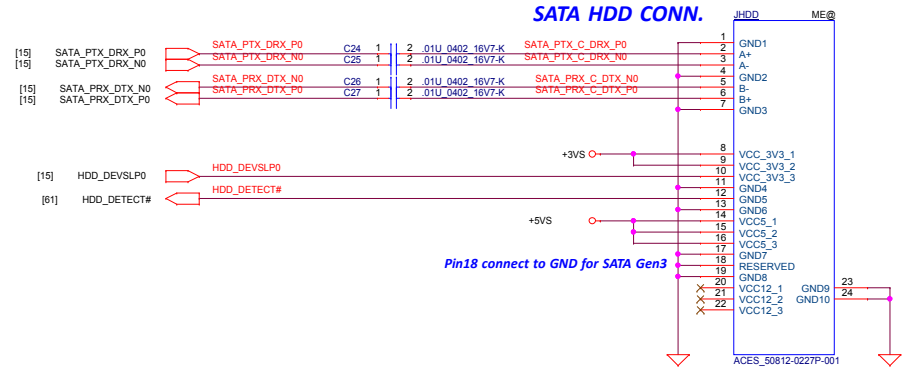
# SATA HDD CONN.

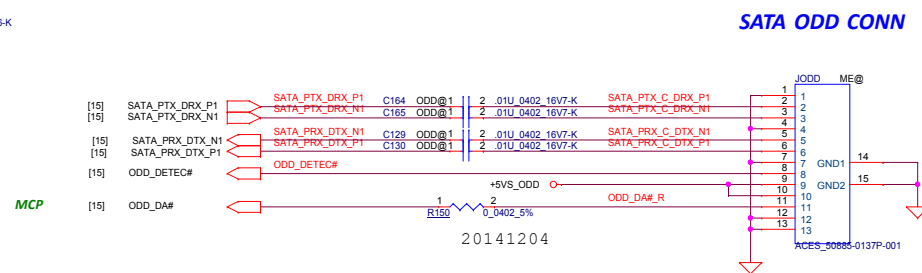
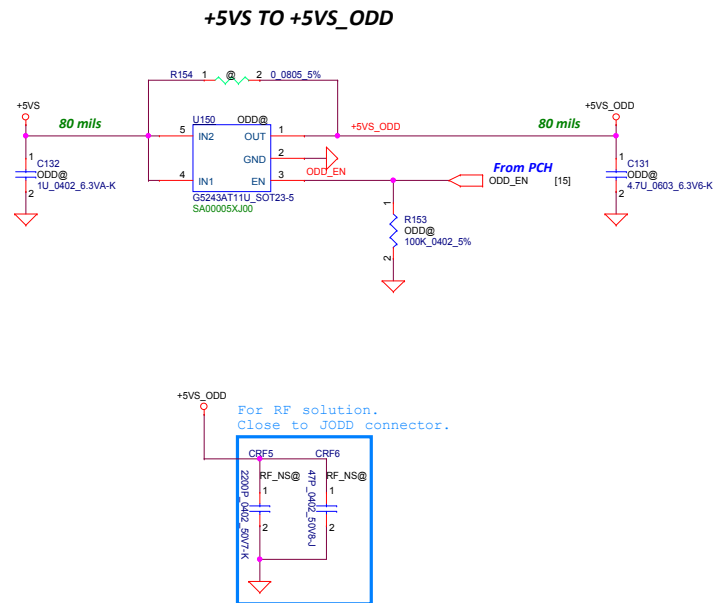
Close to JHDD



Close to JHDD

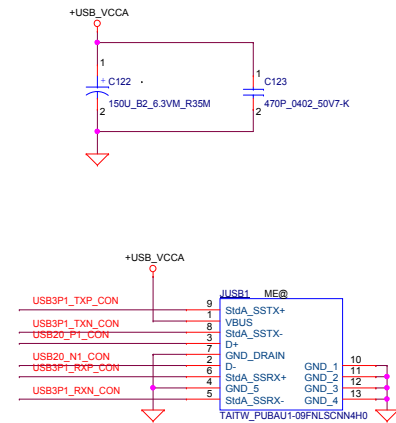
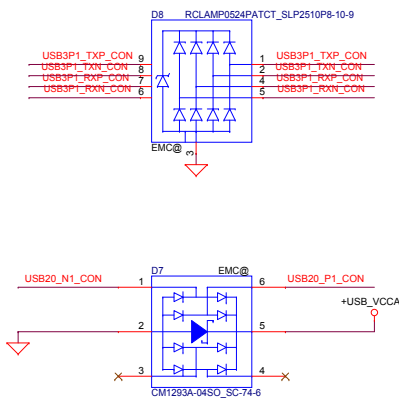
# SATA HDD CONN.



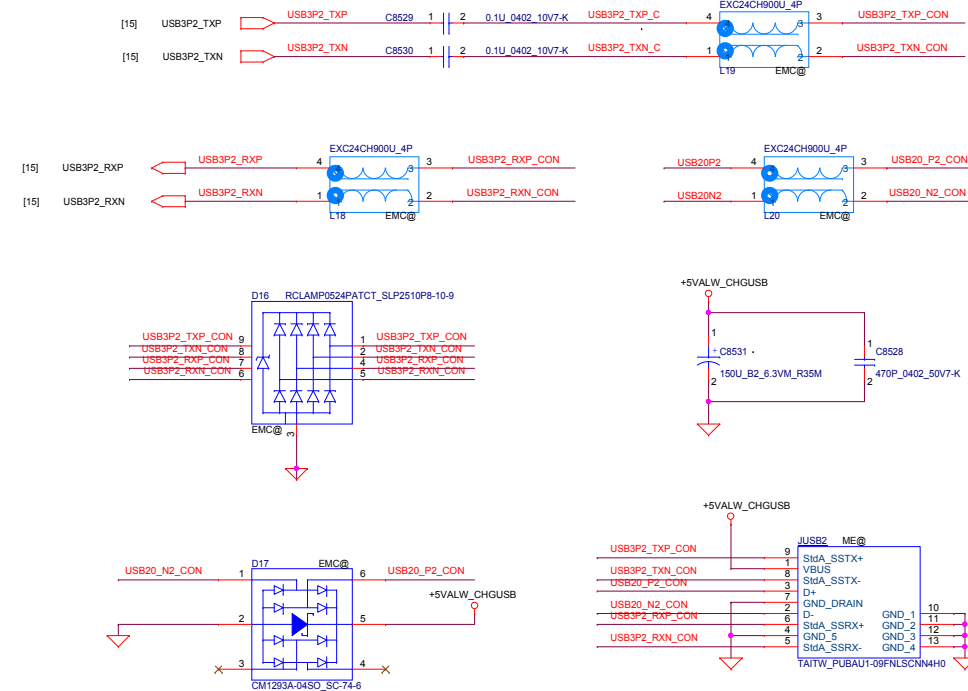





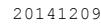
## POWER SWITCH



CLT1	CLT2	CLT3	ILIM_SEL	MOD	
0	0	0	X	DCI	OUT held low
1	1	1	1	CDP	Data Connected and Port Power Mgt. Function Active
1	1	1	0	SDP2	Data Connected
1	1	0	X	SDP1	Data Connected
0	1	0	X	SDP1	Data Connected
1	0	0	X	DCP_Short	Device Forced to stay in DCP BC 1.2 charging mode
1	0	1	X	DCP_Divider	Device Forced to stay in DCP Divider 1 Charging Mode
0	1	1	X	DCP_Auto	Data Disconnected and Port Power Mgt. Function Active
0	0	1	X	DCP_Auto	Data Disconnected and Power Wake Function Active



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20150526

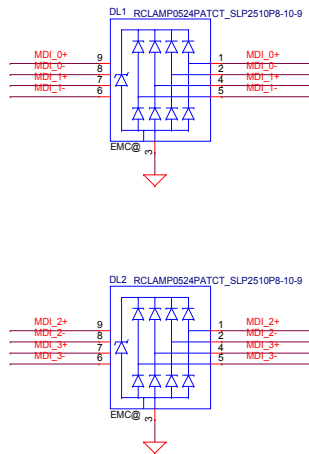
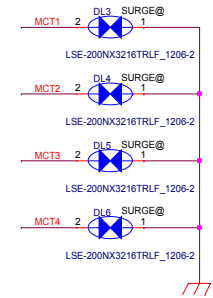
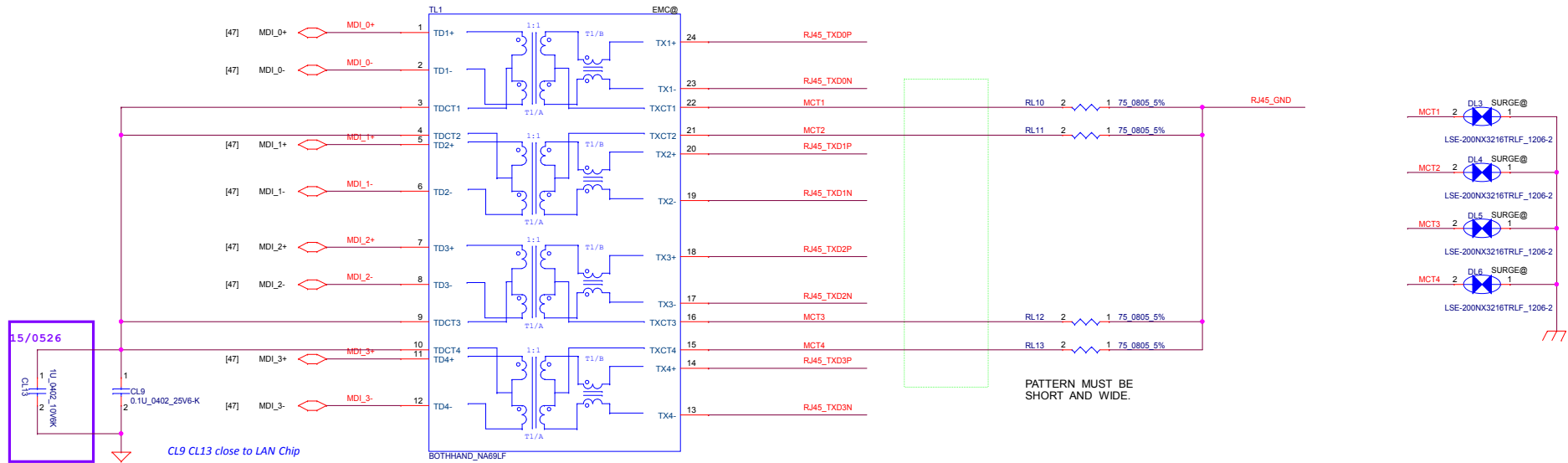
SA00007H610

15/0526

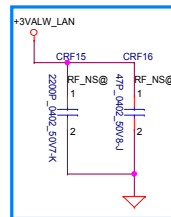
UL1 GBE PHY

vPro Model	Non-vPro Model
I219LM	I219V

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				Date:	Wednesday, September 23, 2015 Sheet 47 of 99

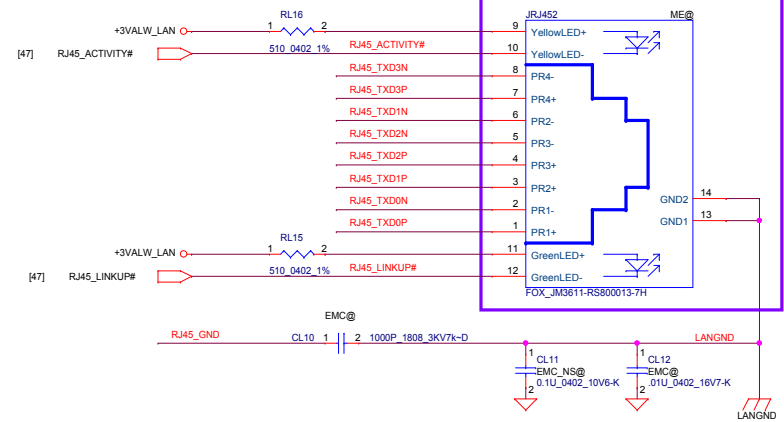


For RF solution.



ME will change CONN on SDV phase.

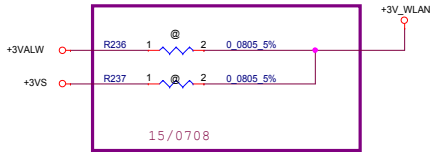
## RJ45 Conn.



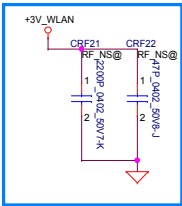
20141231

Security Classification		LC Future Center Secret Data		Title	
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				Custom	
				BE560	
				Rev 0.1	
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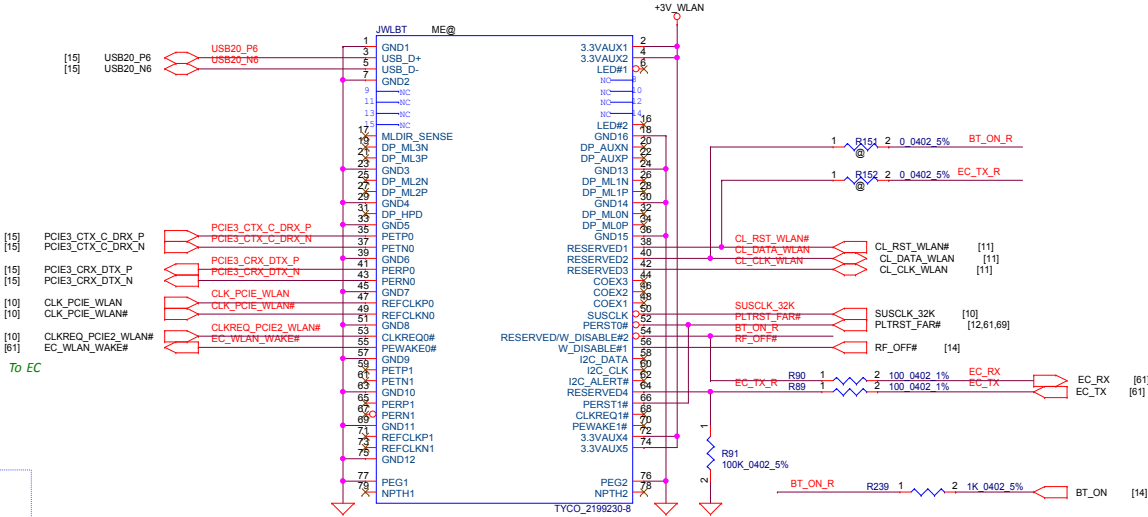
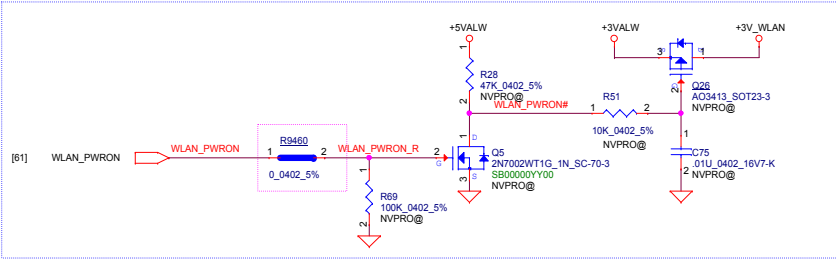
TYPE-A NGFF SLOT FOR WLAN  
3.2H CONNECTOR

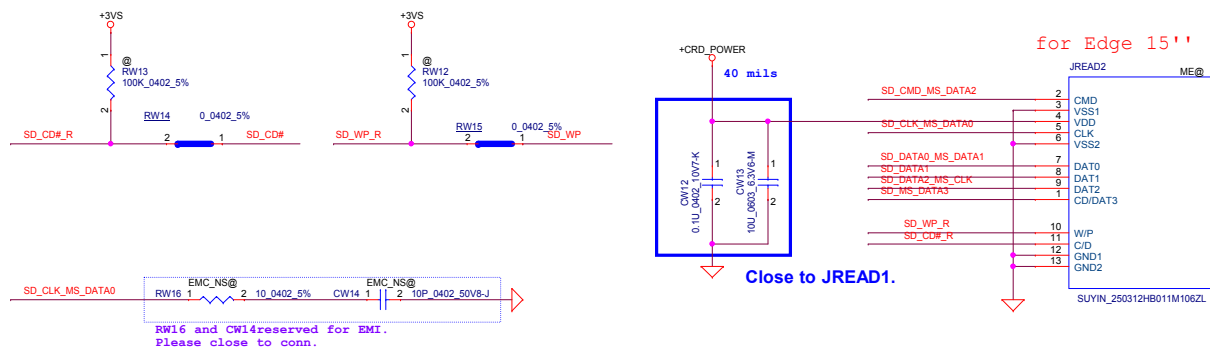
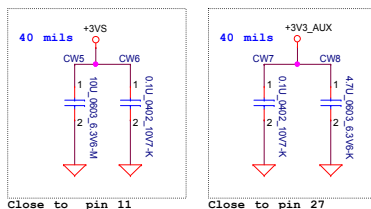
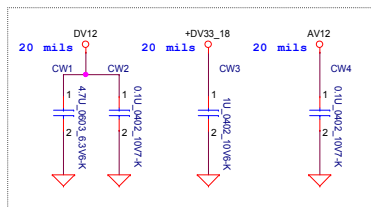
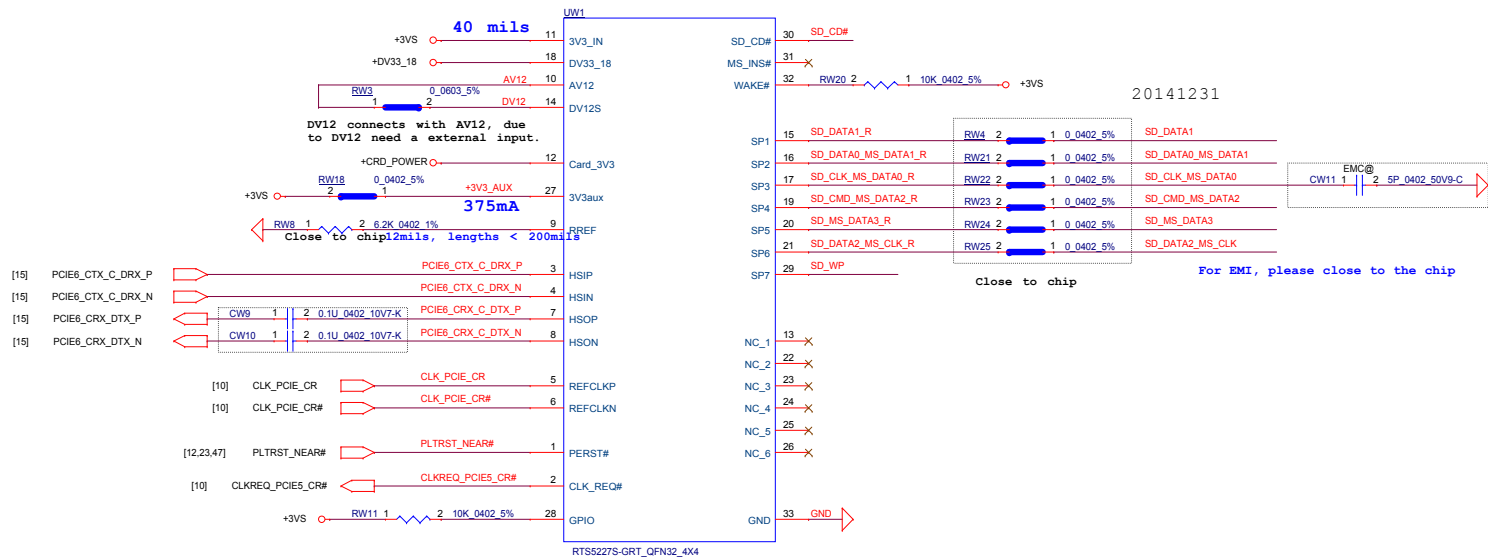


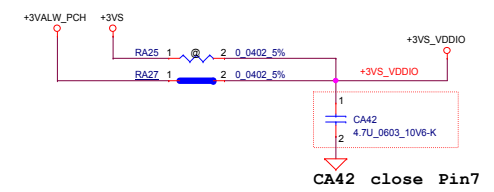
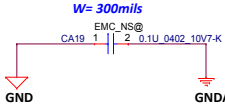
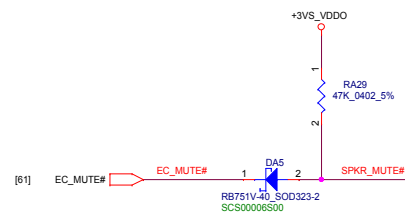
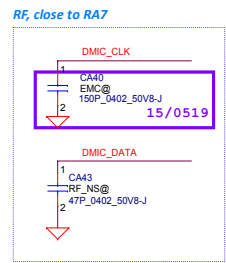
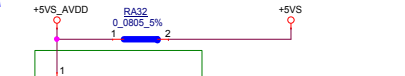
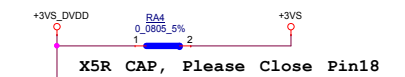
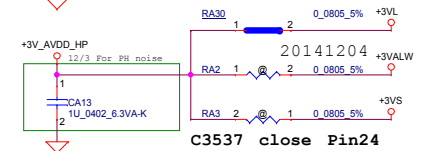
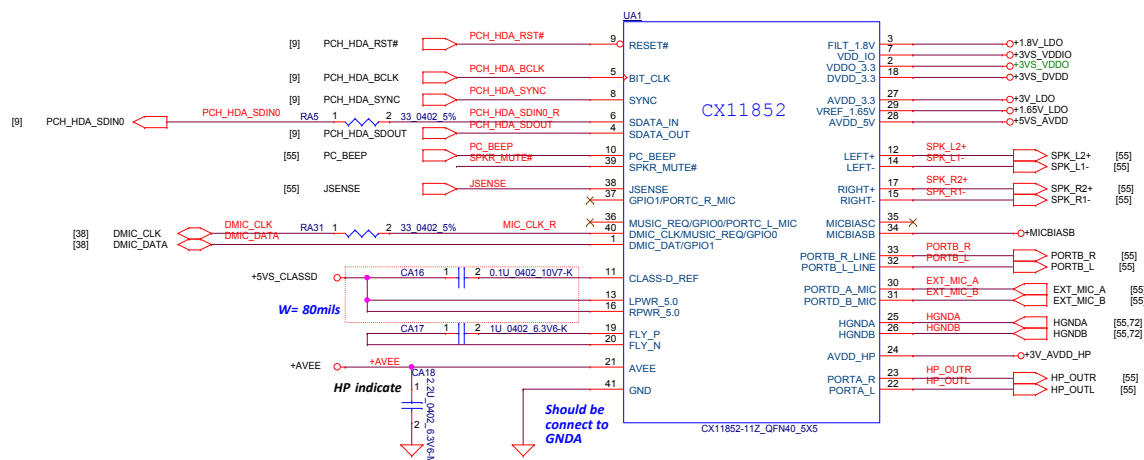
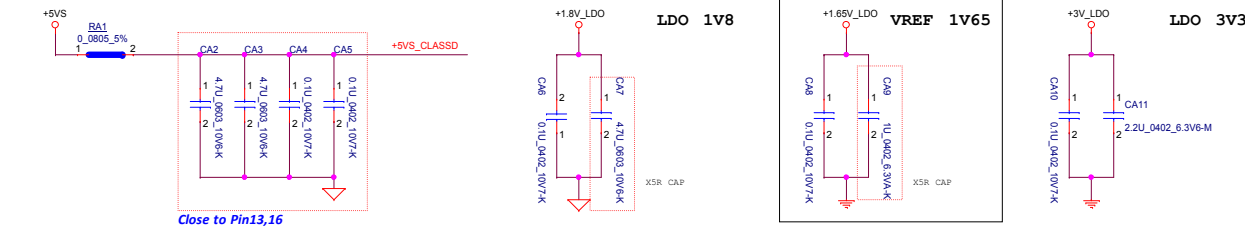
For RF solution.



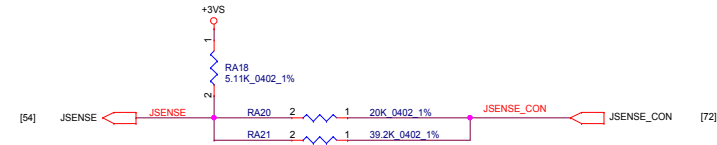
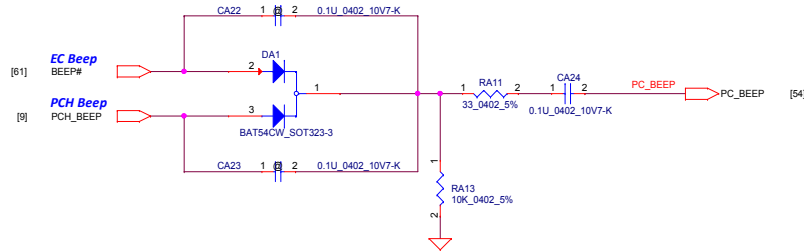
VPRO SKU : R48(@), R70(VPRO@)



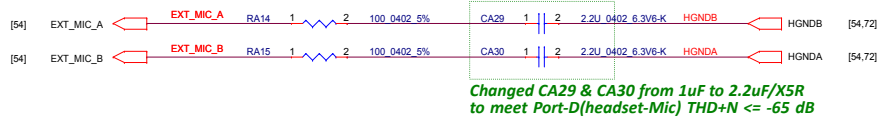




## PC Bleep

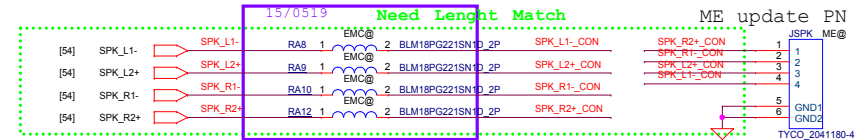


**EXT. MIC/LINE IN** Apple --> EXT\_MIC\_A, HGND B  
Nokia --> EXT\_MIC\_B, HGND A

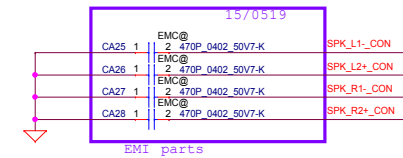
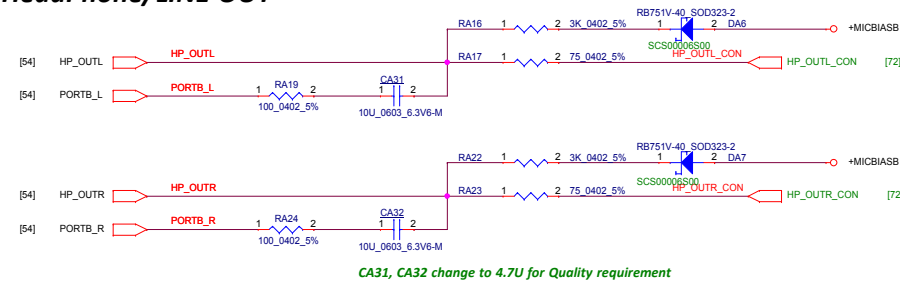


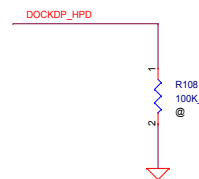
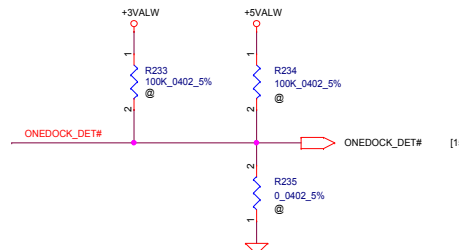
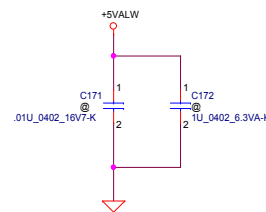
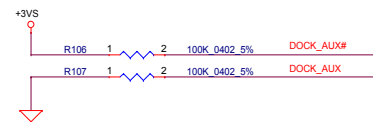
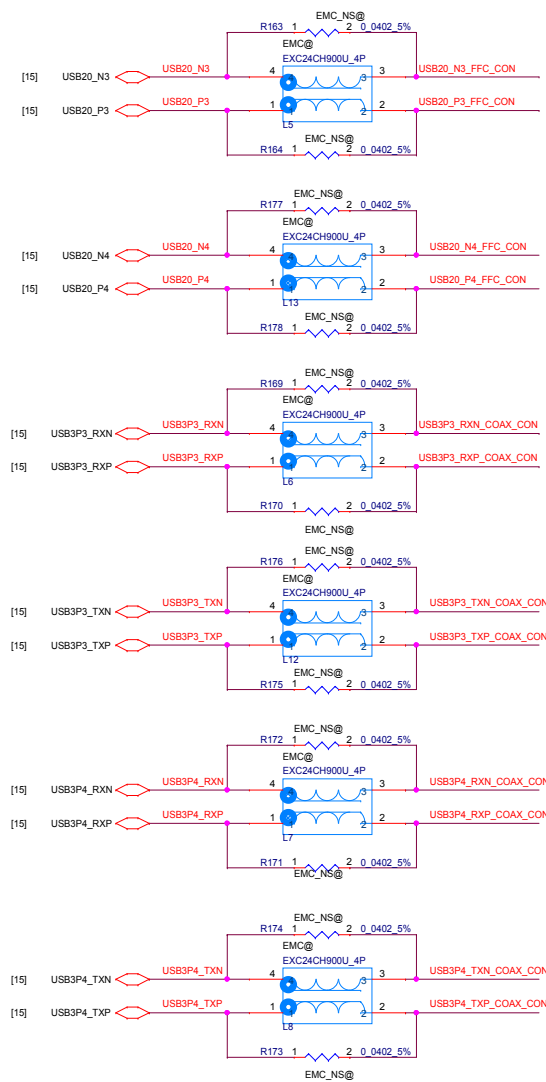
## Speaker OUT

## SPK CONN.

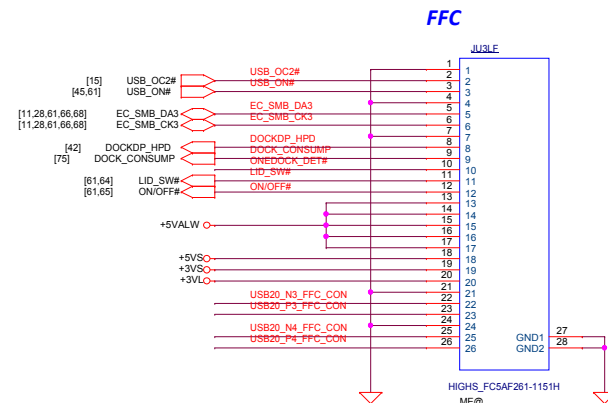
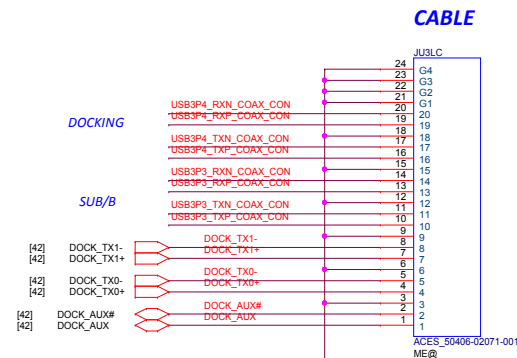


## HeadPhone/LINE OUT

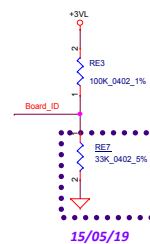
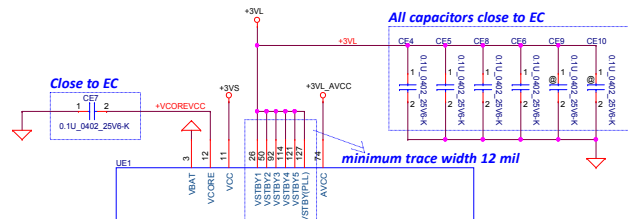
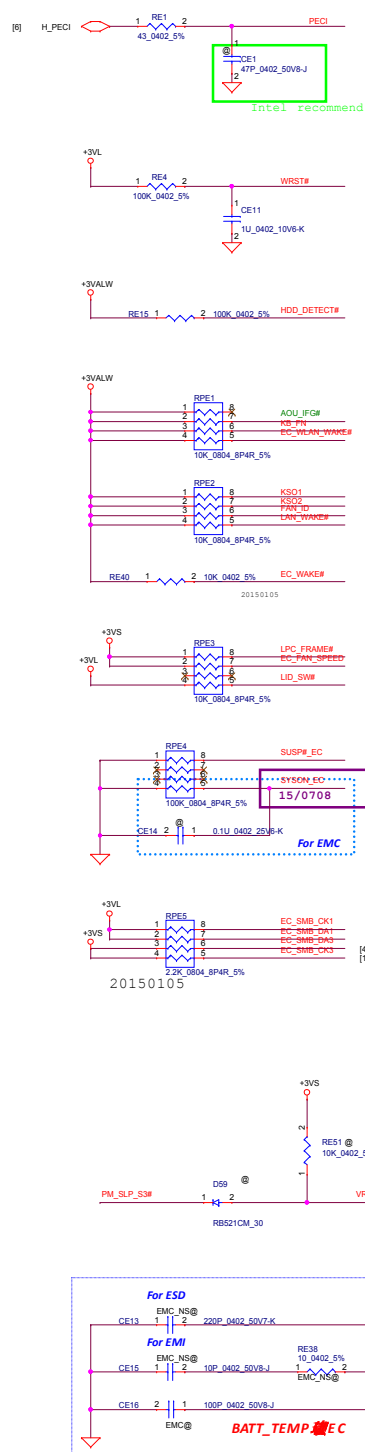




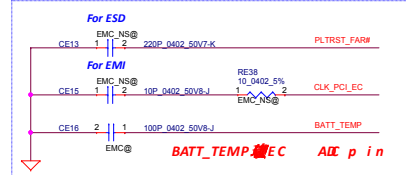
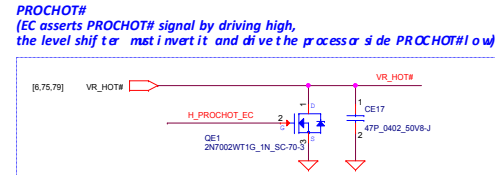
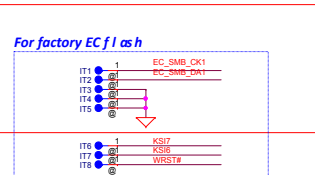
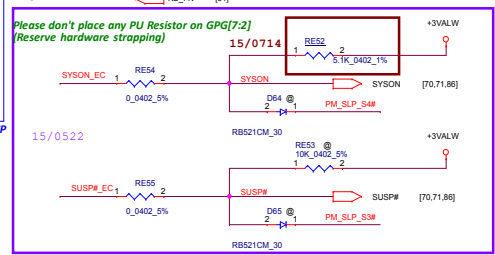
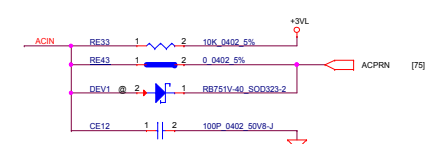
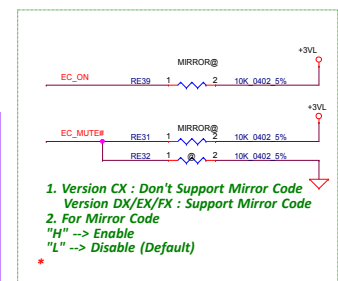
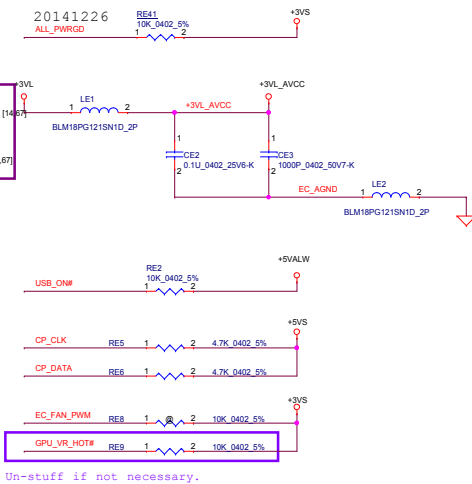
1. AC Capacitor place on Sub/B  
2. Need to check with MUX IC vendor whether st ill need AC cap bet ween MUX IC and dev ce



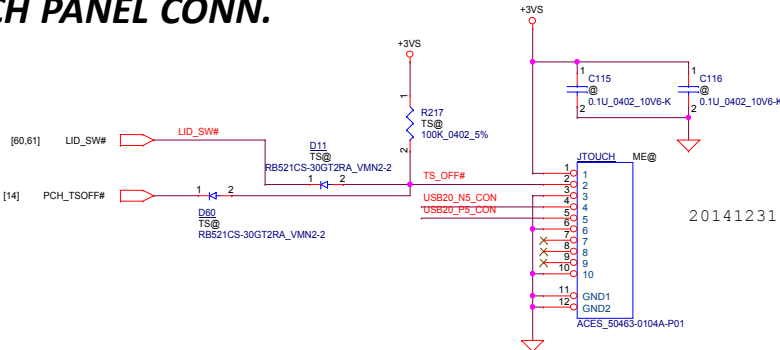
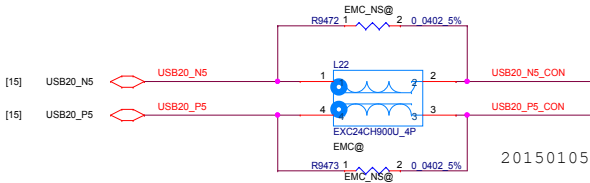




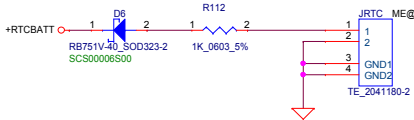
<b>Vcc</b>	0.3V +/- 5%					
<b>RE3</b>	100K +/- 1%					
<b>Board ID</b>	<b>RE7</b>	<b>VAD_BID min</b>	<b>VAD_BID typ</b>	<b>VAD_BID max</b>	<b>Phase</b>	
0	0K +/- 5%	0 V	0 V	0 V	SDV	
1	8.2K +/- 5%	0.216 V	0.250 V	0.289 V	FVT	
2	18K +/- 5%	0.436 V	0.503 V	0.538 V	SIT	
3	33K +/- 5%	0.712 V	0.819 V	0.875 V	SVT	
4	4.7K +/- 5%	0.141 V	0.148 V	0.155 V		
5	24K +/- 5%	0.612 V	0.638 V	0.664 V		



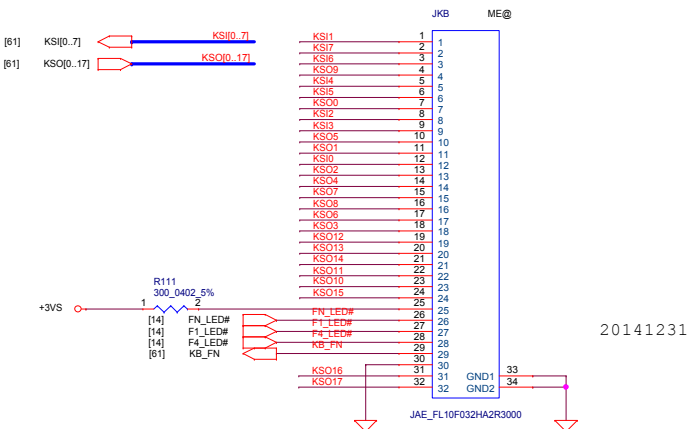
TOUCH PANEL CONN.



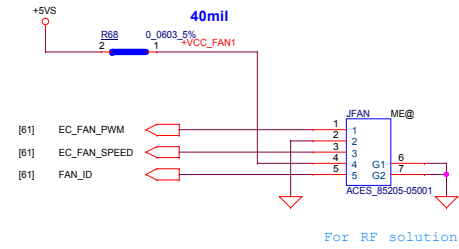
RTC CONN.



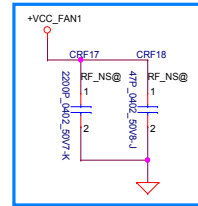
KB CONN



## FAN CONN.



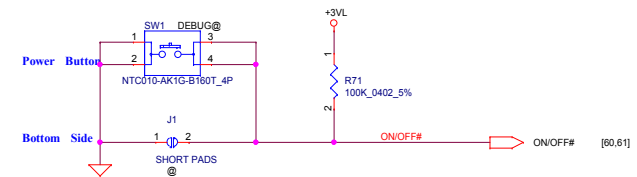
運轉線板 de fi B



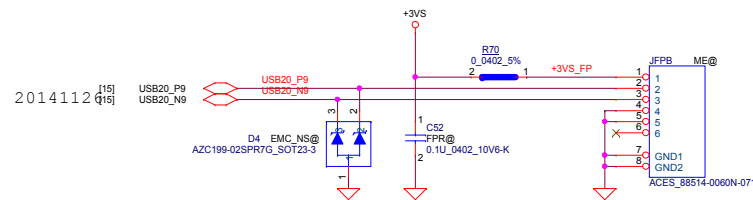
## PWR BTN/LID SW CONN.

For 14" on board  
For 15" on Sub/B

ON/OFF Switch --> 轉 Sub/B



## FingerPrint CONN.

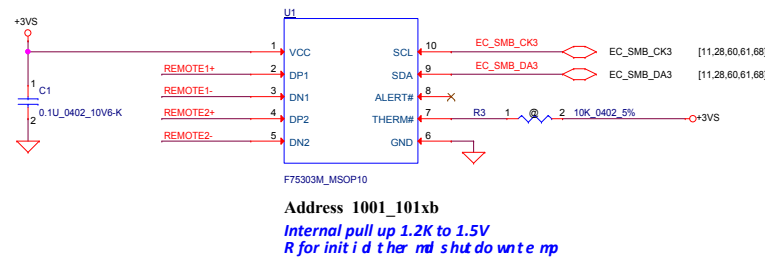


Lid Switch --> 轉 Sub/B

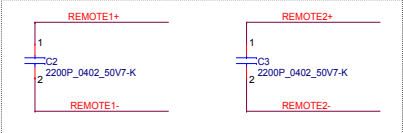
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Thermal Sensor

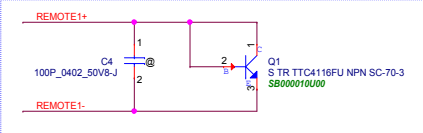
Thermal Sensor  
placed near by VRAM



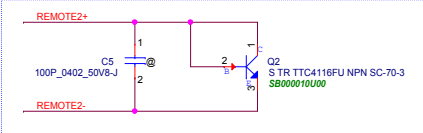
Close to U1



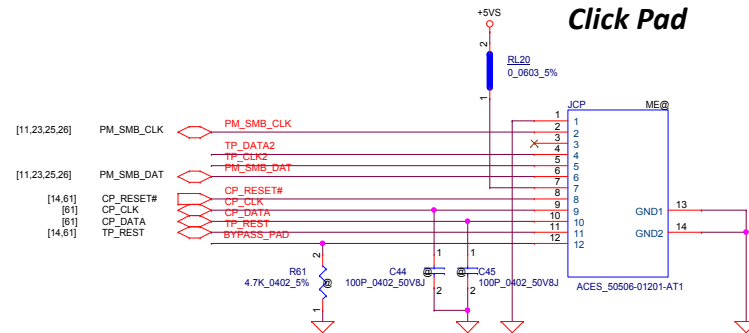
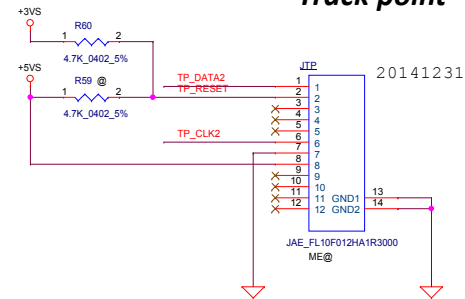
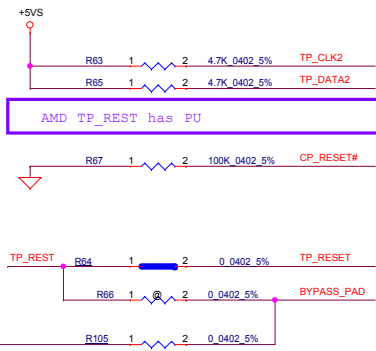
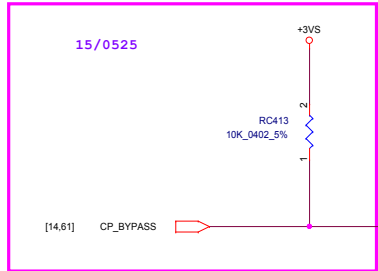
Close to +VCC\_CORE

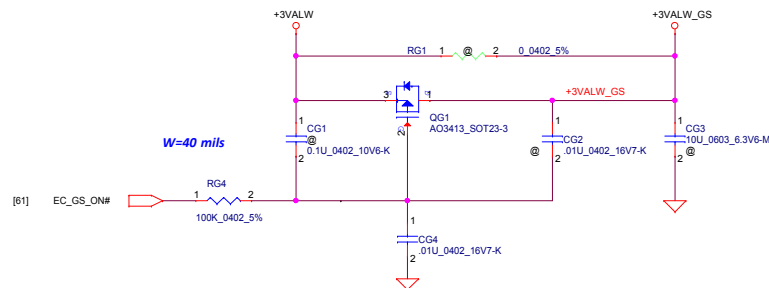


Close JDIMM1&JDIMM2



REMOTE2+/-:  
Trace width/space:10/10 mil  
Trace length:<8"

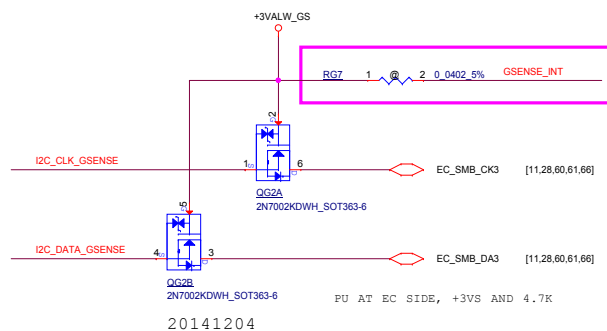




## APS G-Sensor

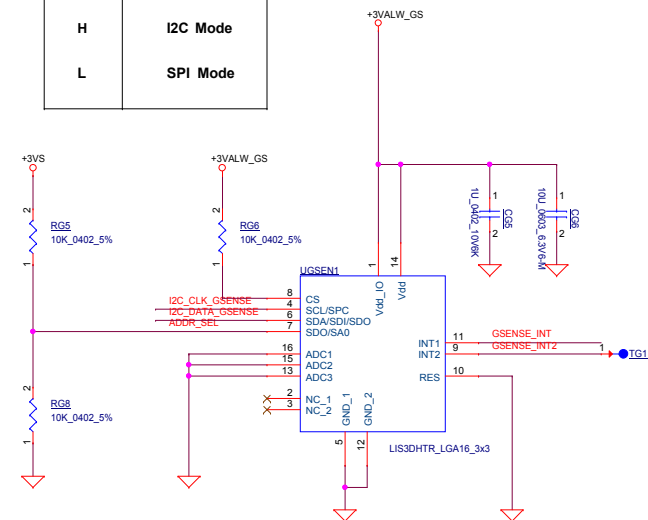
TABLE

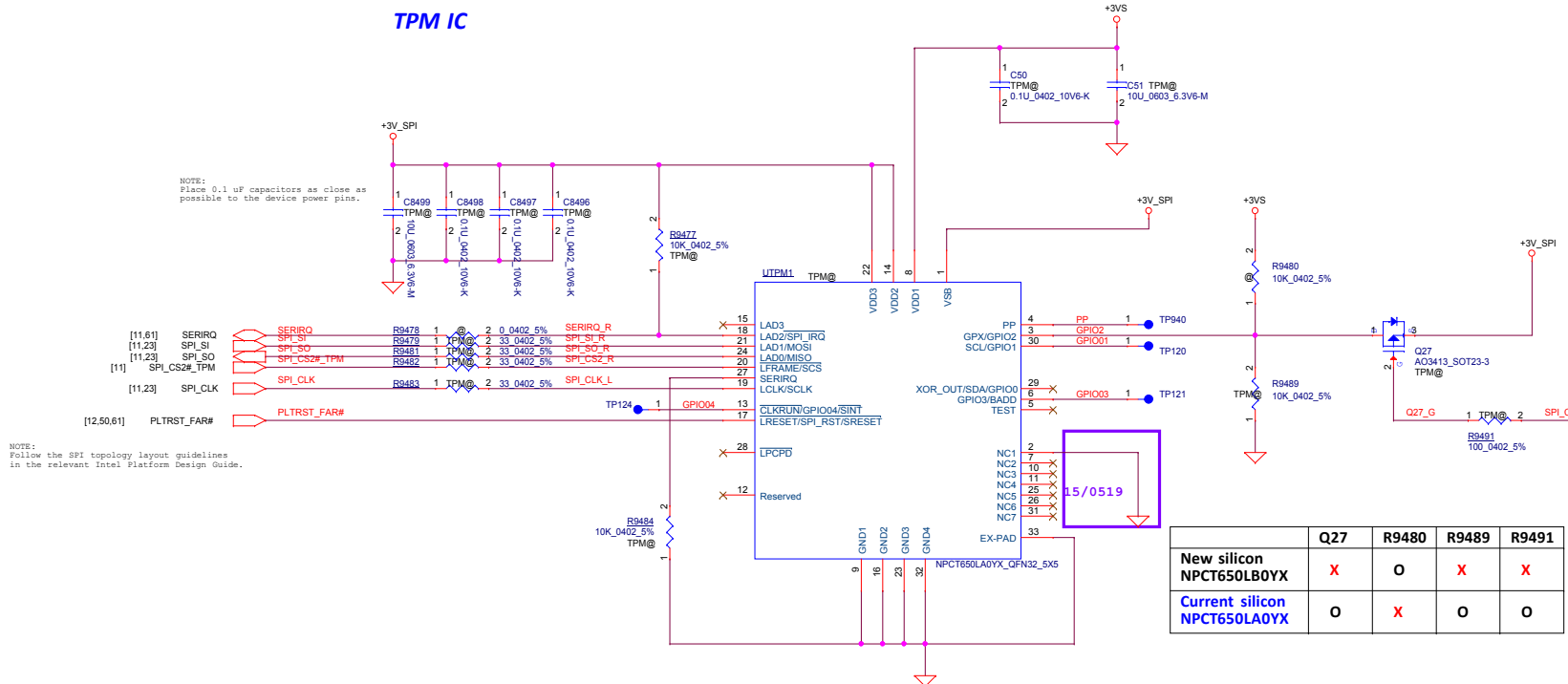
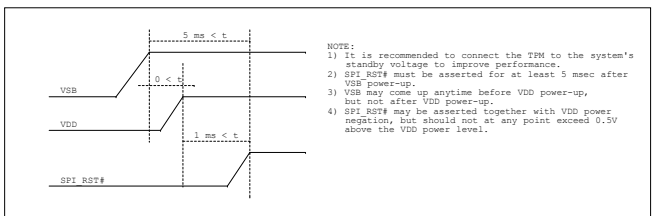
P/N	ADDR_SEL	Address
LIS3DH	H	32h (W) & 33h (R)
	L	30h (W) & 31h (R)
KX023-1025	H	3Eh (W) & 3Fh (R)
	L	3Ch (W) & 3Dh (R)



TABLE

P/N	Mode Selection
H	I2C Mode
L	SPI Mode



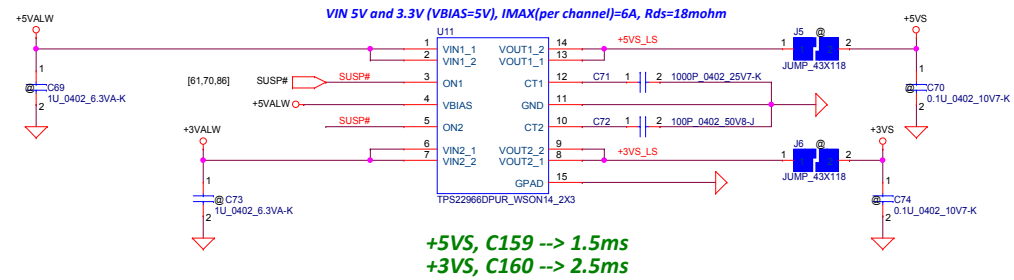


	Q27	R9480	R9489	R9491
New silicon NPCT650LB0YX	X	O	X	X
Current silicon NPCT650LA0YX	O	X	O	O

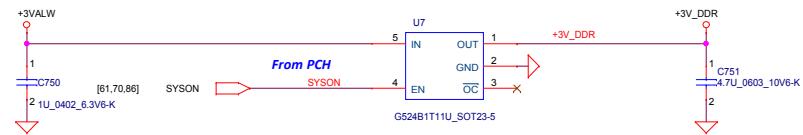




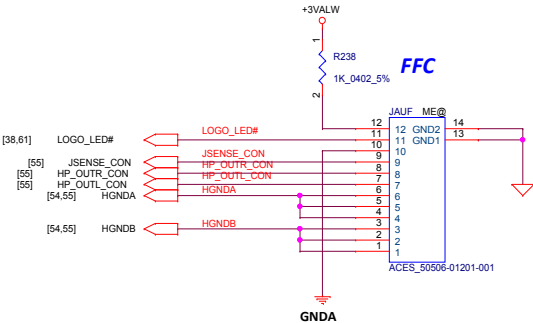
**Load Switch**  
**+5VALW To +5VS**  
**+3VALW To +3VS**



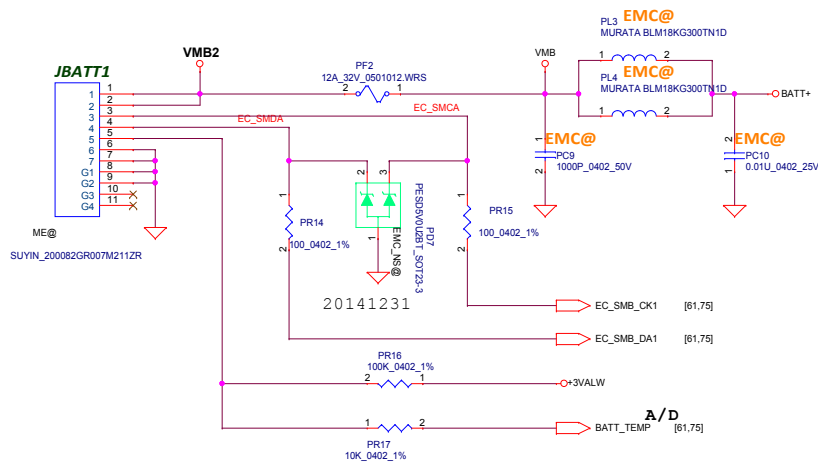
**+3VALW to +3V\_DDR**



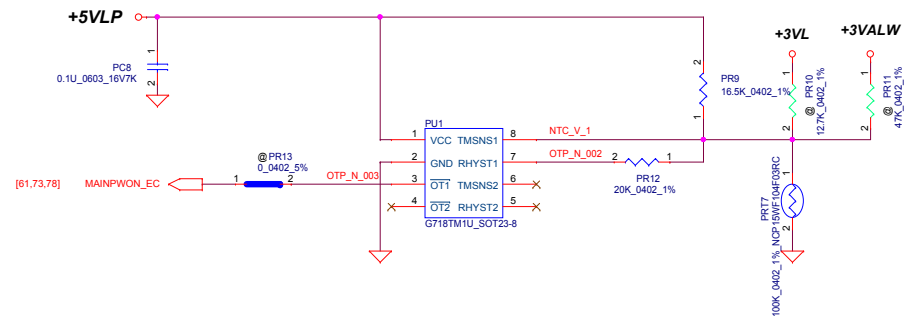
For Edge 15" Audio board CONNECTOR





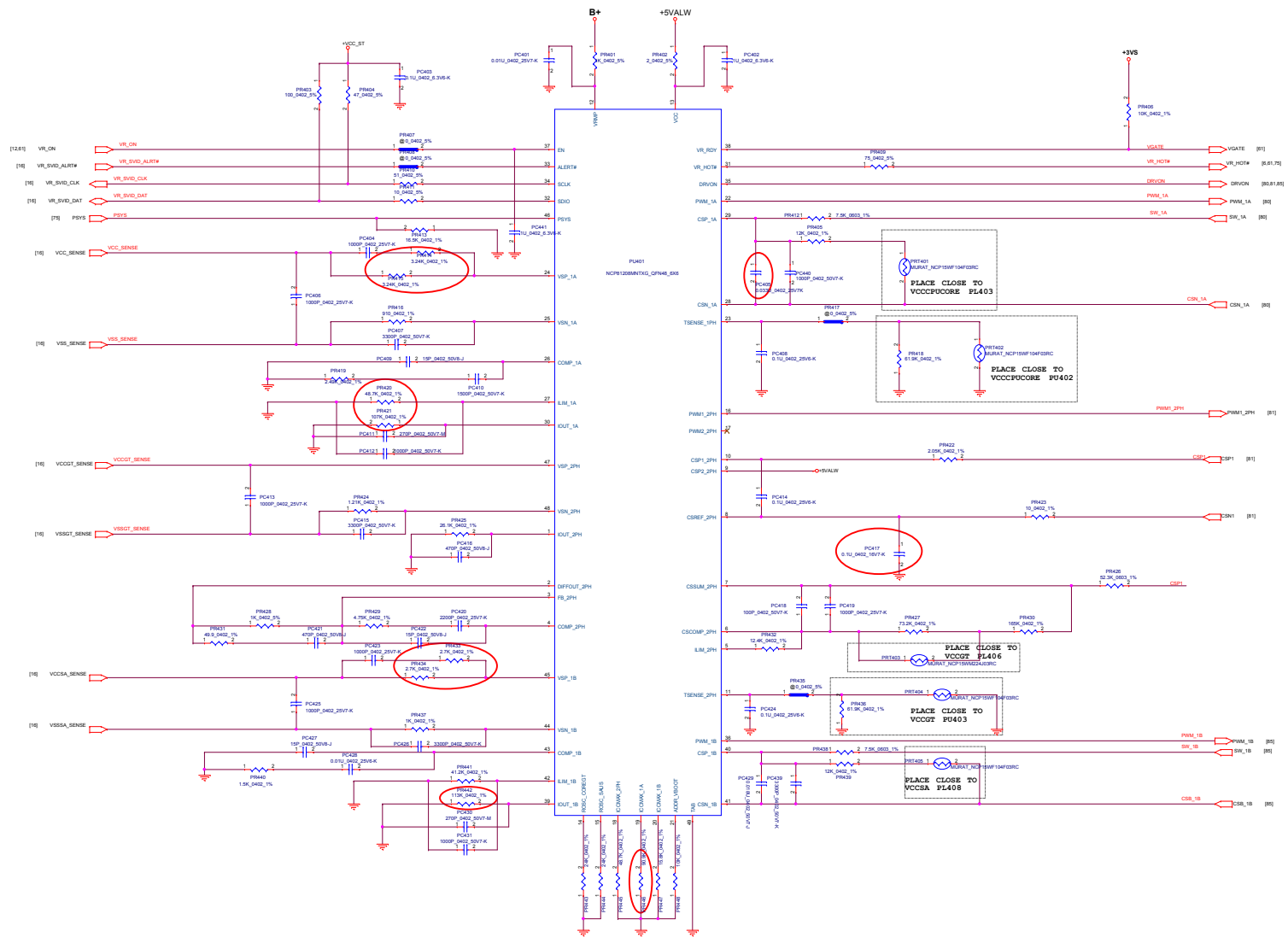


**PRT7 under CPU bottom side :**  
**CPU thermal protection at 93  $\pm$  3 degree C**  
**Recovery at 56  $\pm$  3 degree C**



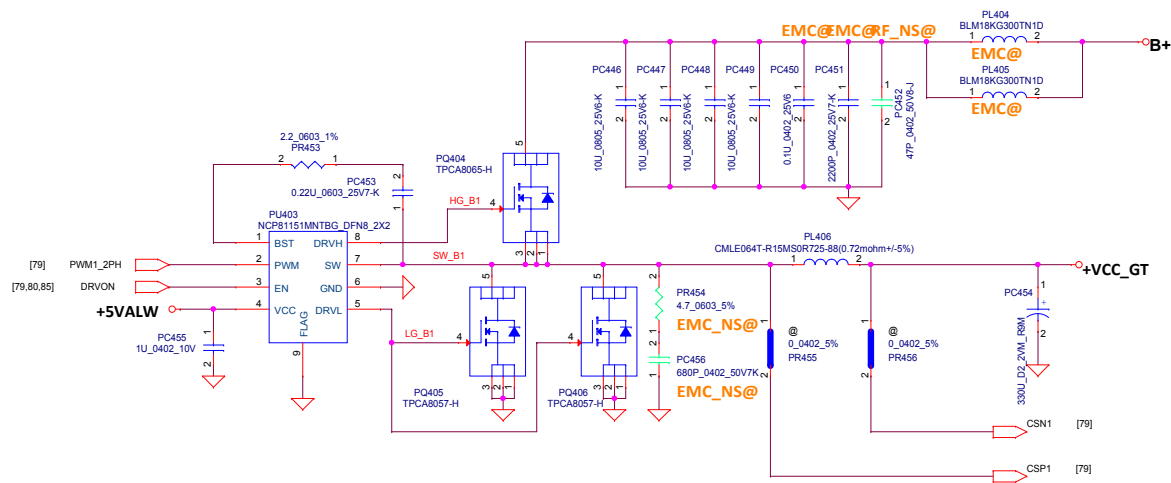








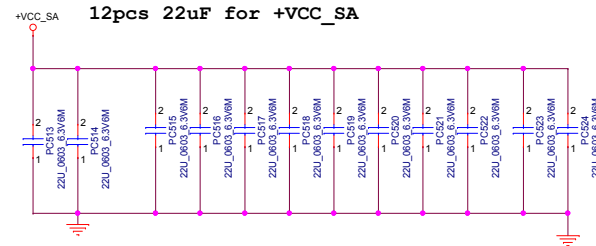
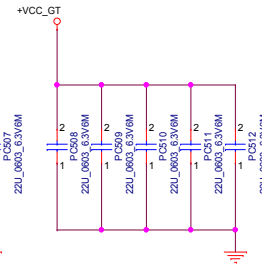
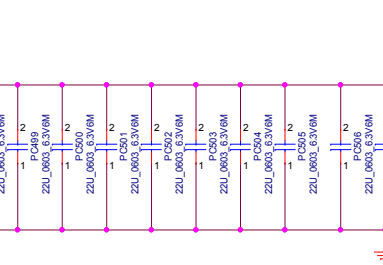
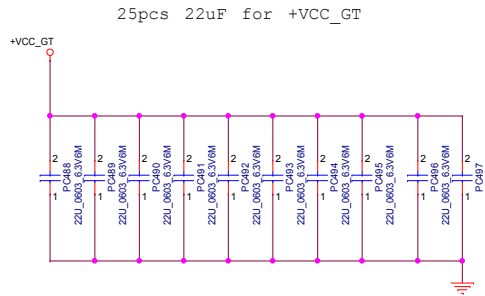
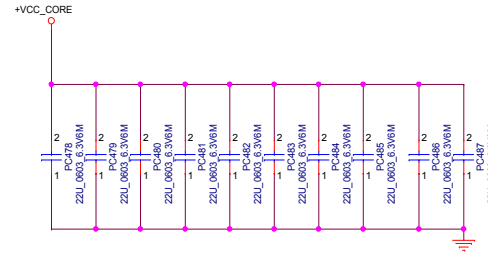
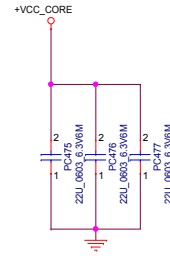
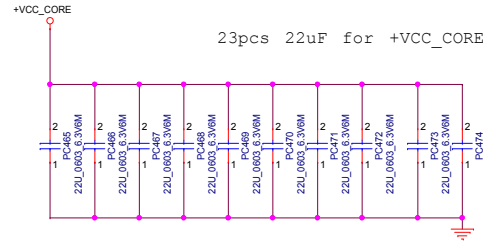




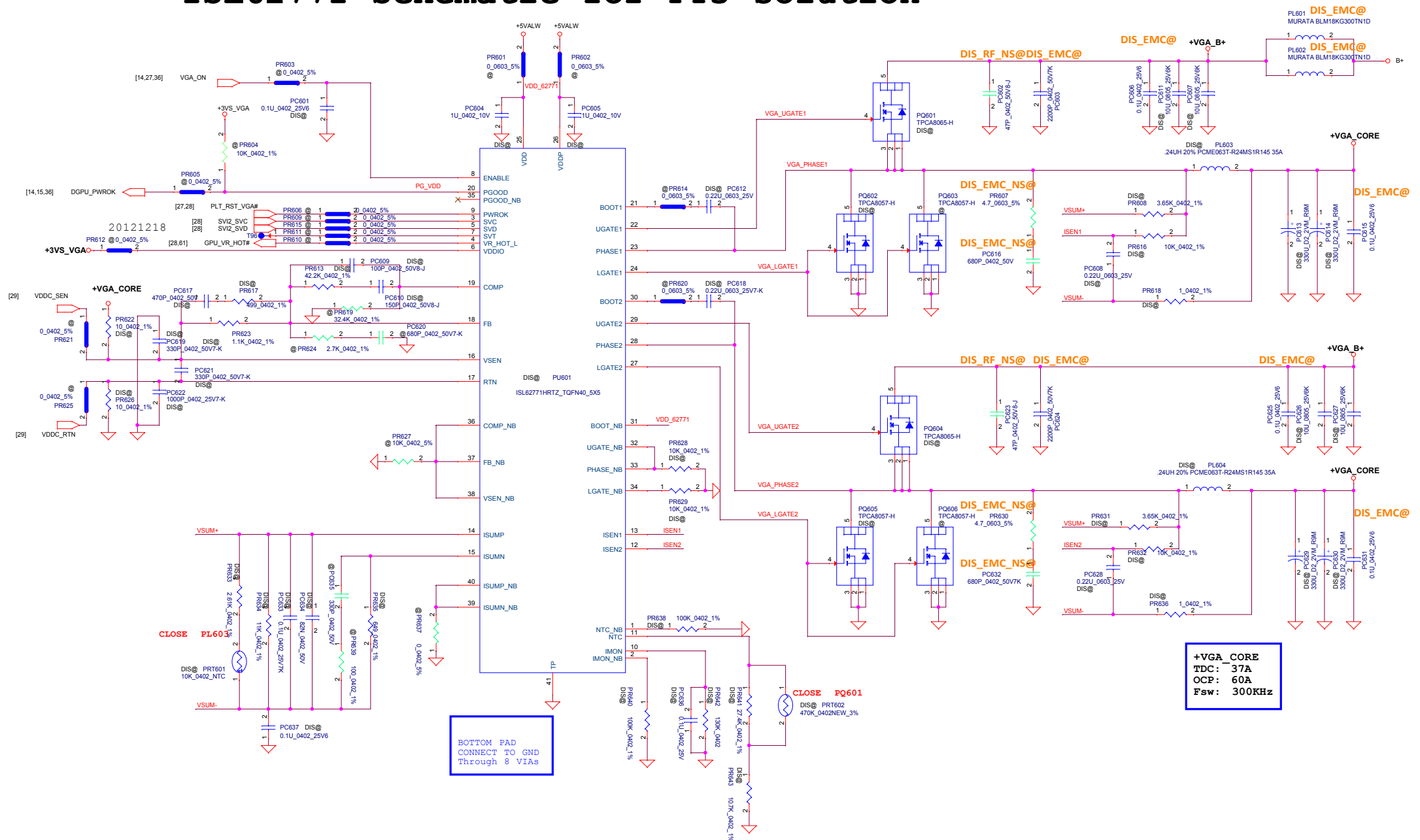
**+VCC\_GT**  
**TDC= 18A**  
**IccMAX=31A**  
**OCp min = 40A**


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				AIVL2 NM-A351	
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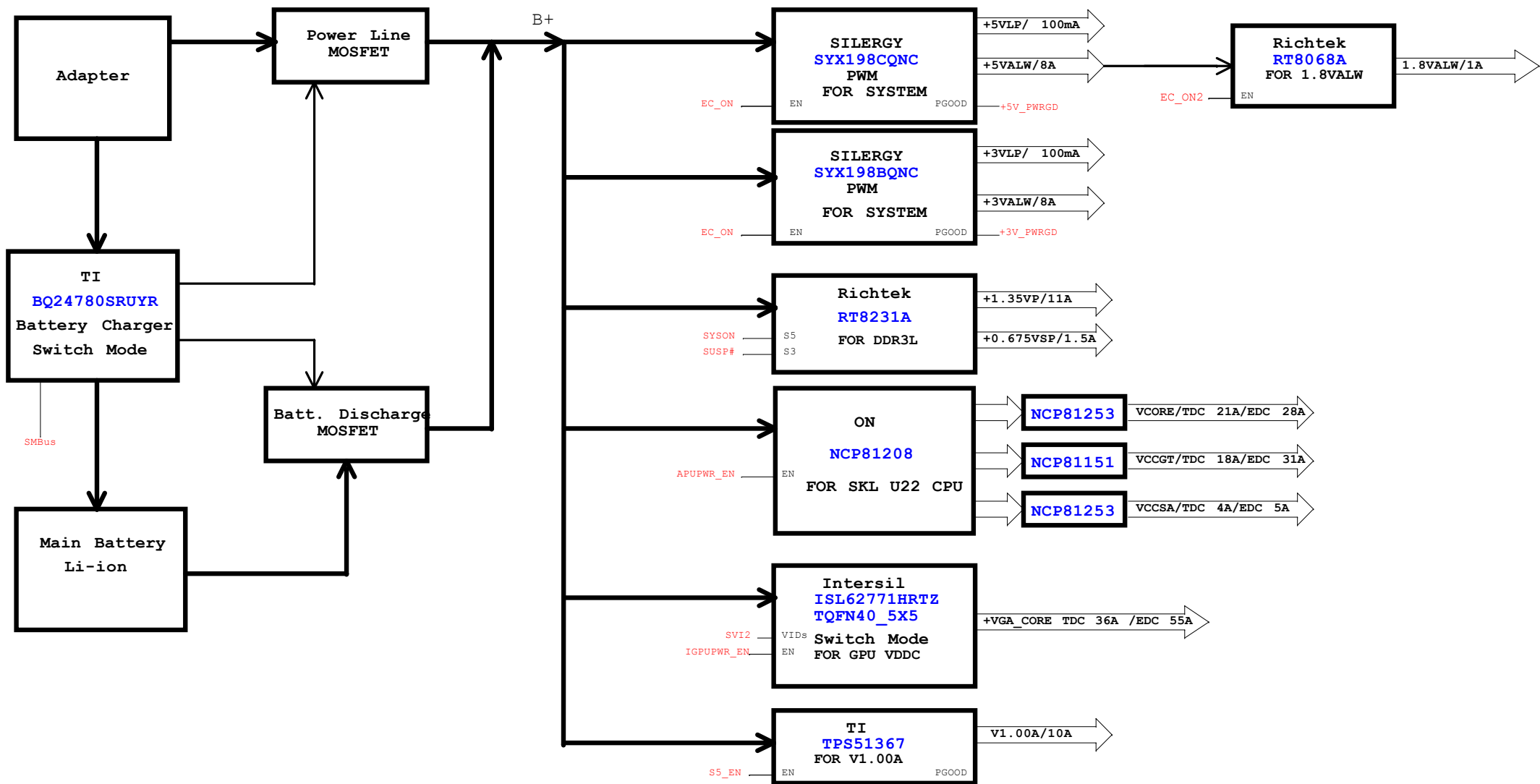
Based on PDDG rev 0.7 Table 5-1.

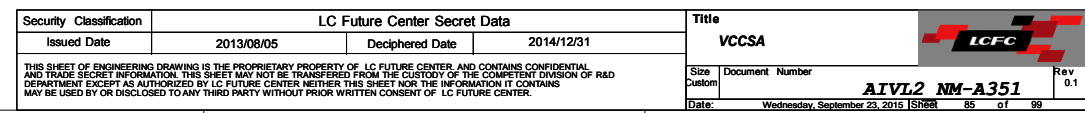


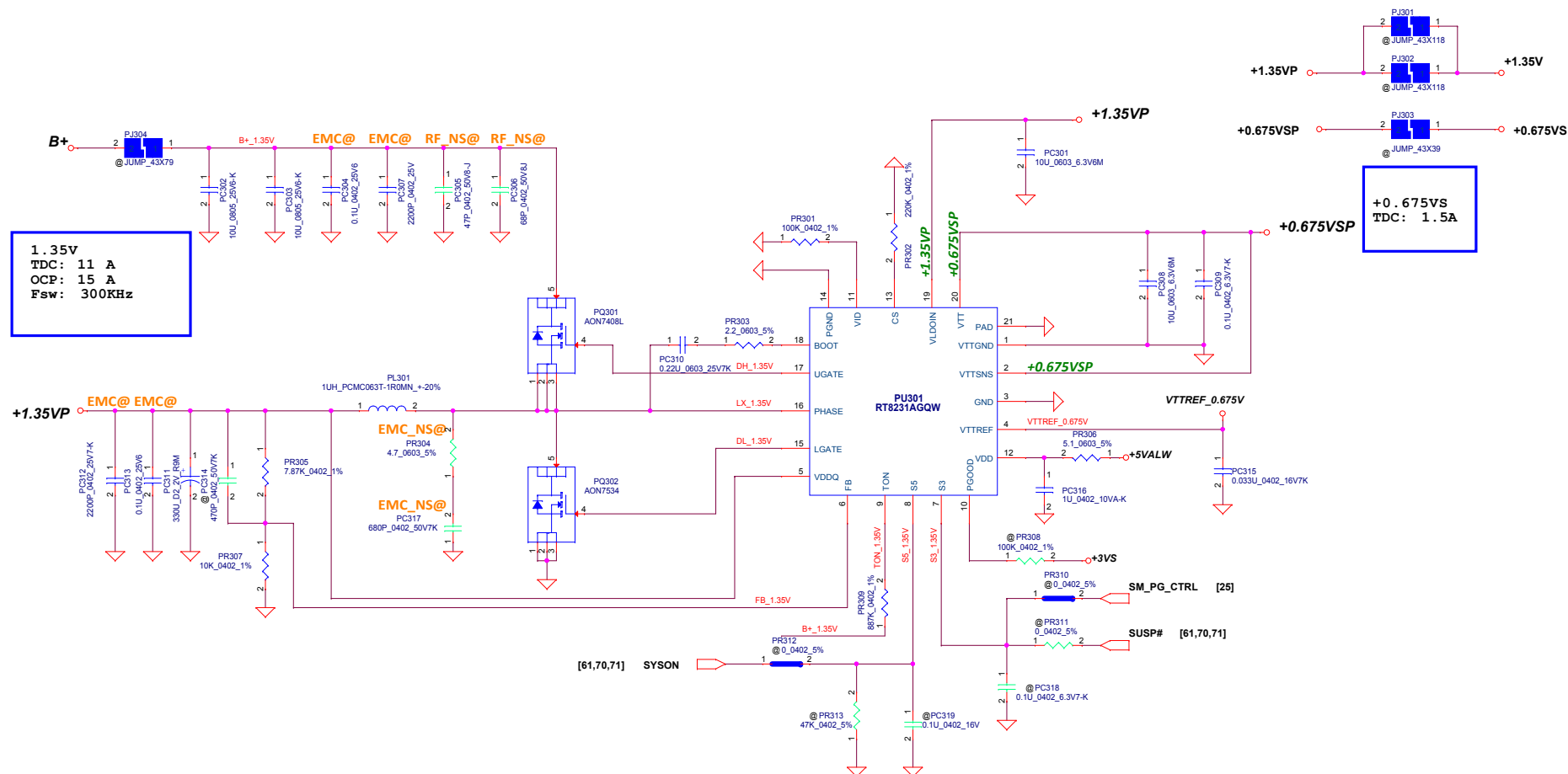
## ISL62771 Schematic for FT3 solution

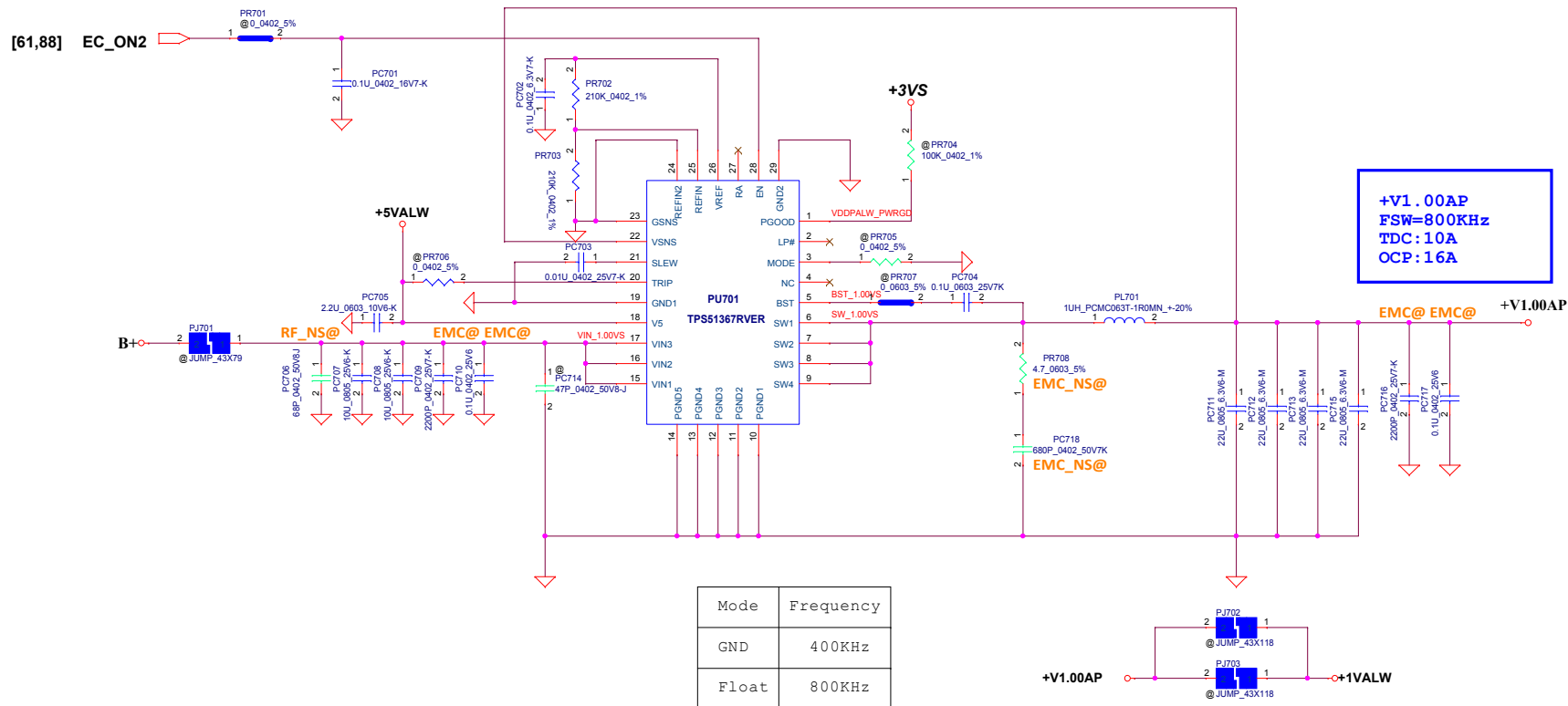


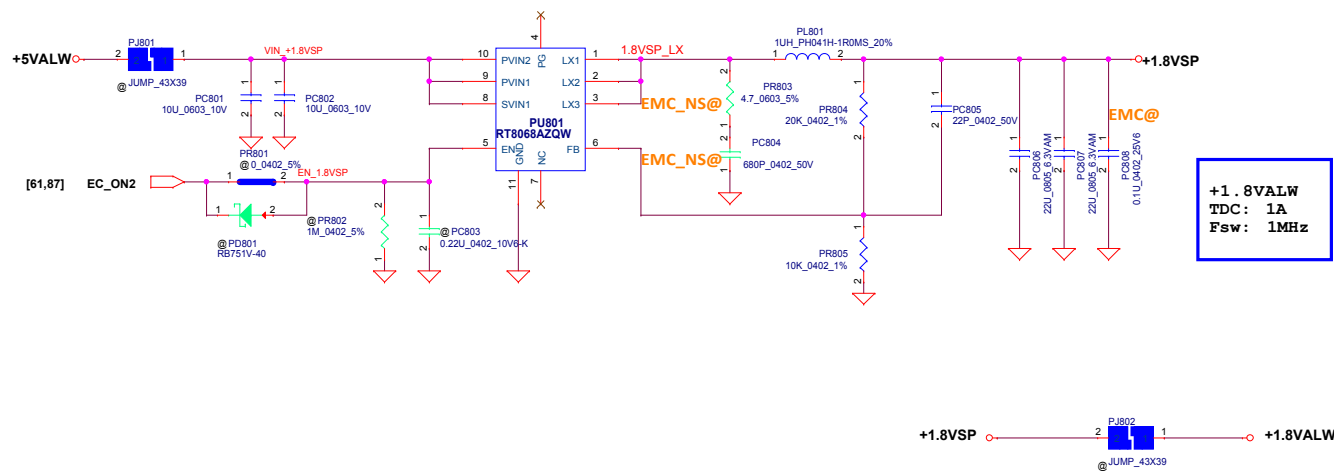
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Screw Hole



Center Zero

PCB Fedcal Mark PAD

